

SPring-8

Industrial Applications

- **Electronics**

- Gate oxide films for LSI
- Thin films for storage devices, etc

- **materials**

- Safety tire, fibers
- Metal coats, etc

- **Energy & environments**

- Detection of metals in human hair
- battery

JASRI Satoshi Komiya

Industrial Applications of SR

Characterization of materials

- Structure, Chemical state, Contamination, etc.
thin films for electronic devices; LSI, HDD, lasers
metals, polymers, batteries, catalyses
- high **brilliant** source, x-ray; big machine

Production technology

- lithography, photo-assisted etching or deposition
- high **flux** source, ultra-violet-soft x-ray;
small machine



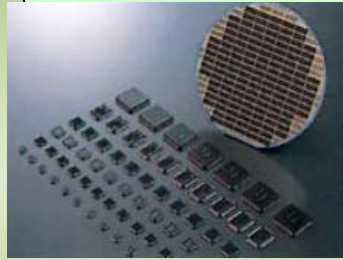
Industrial Applications

- Films for ULSI, semiconductors
- HDD, DVD
- Semiconductor laser

- Steel & Coats on steel
- Al included bubbles

- Tires
- Fibers

electronics



Metals & Soft materials

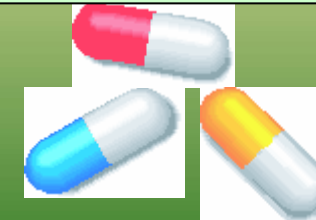


Synchrotron radiation

Energy & Environment



Life science



Others

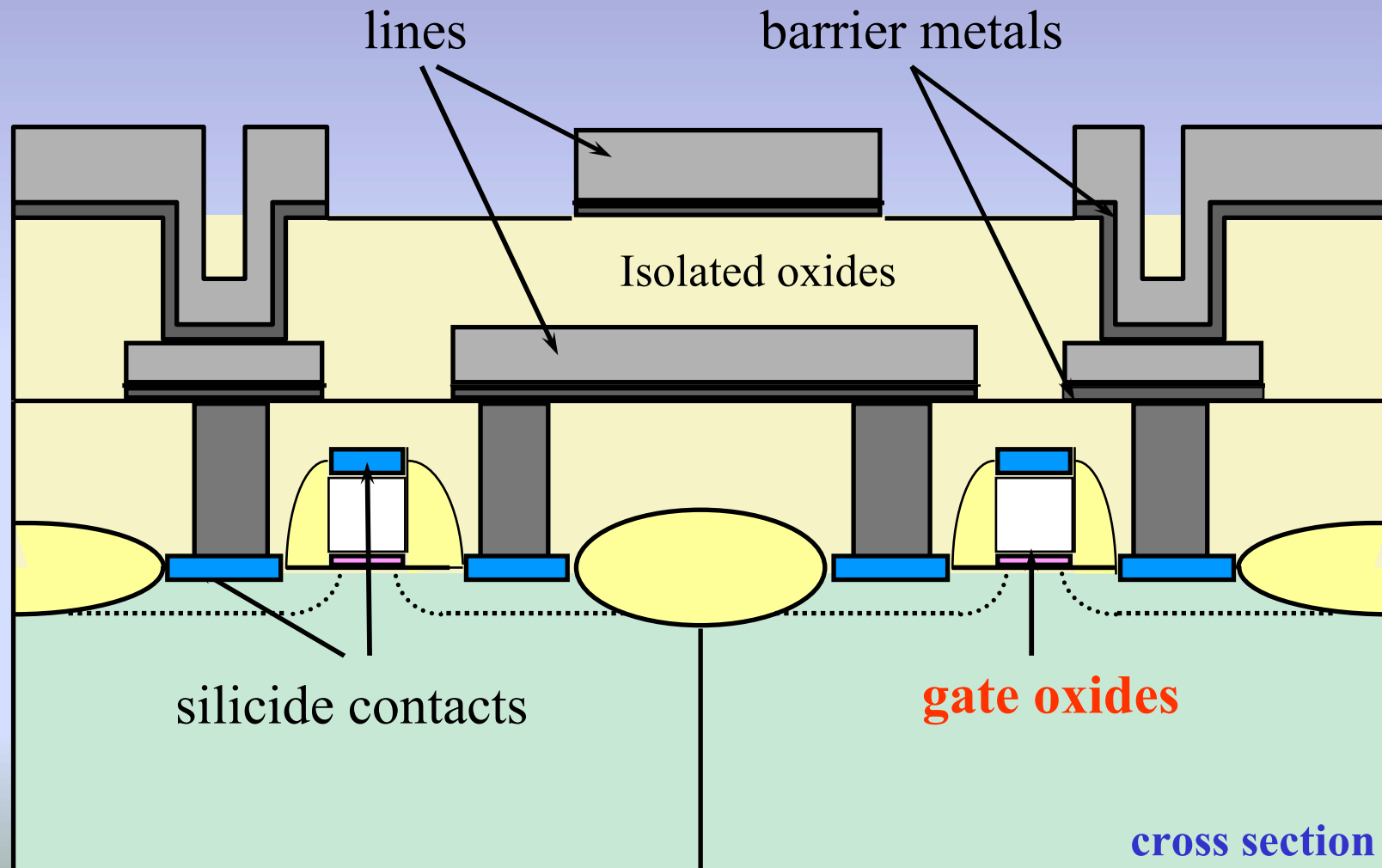
- Building materials
- Catalysis
- Insects

- Batteries: fuel cell & Li-ion
- Analysis of contamination elements
- Catalysts for environment

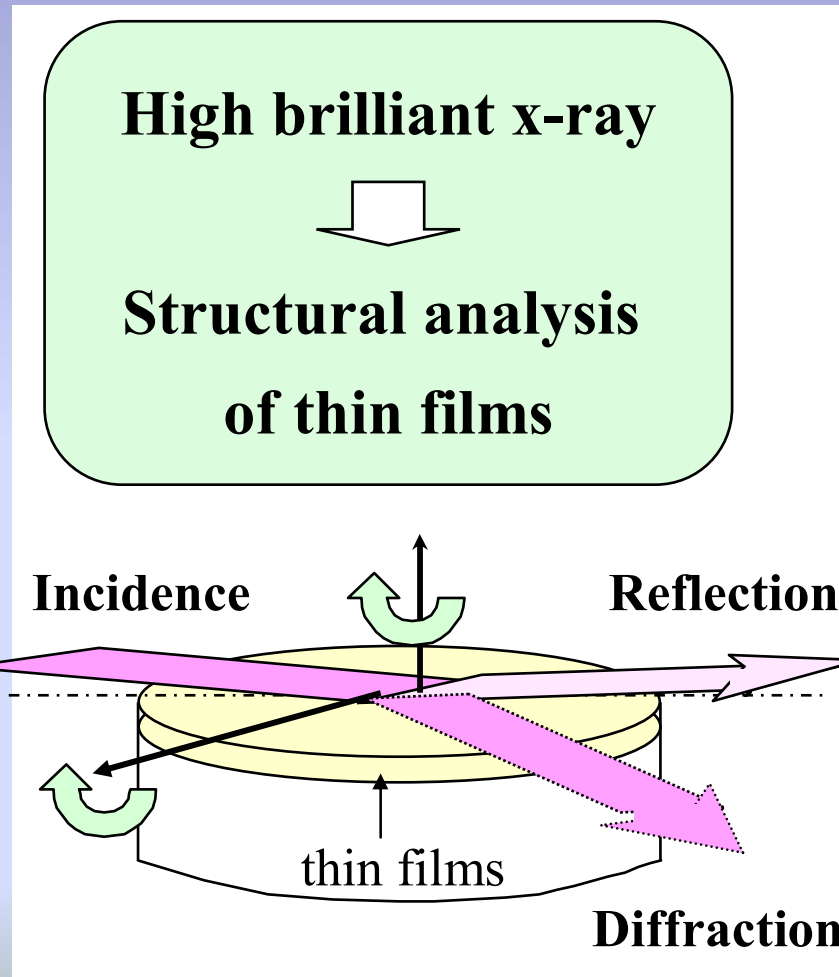
•medicine

CMOS Structure

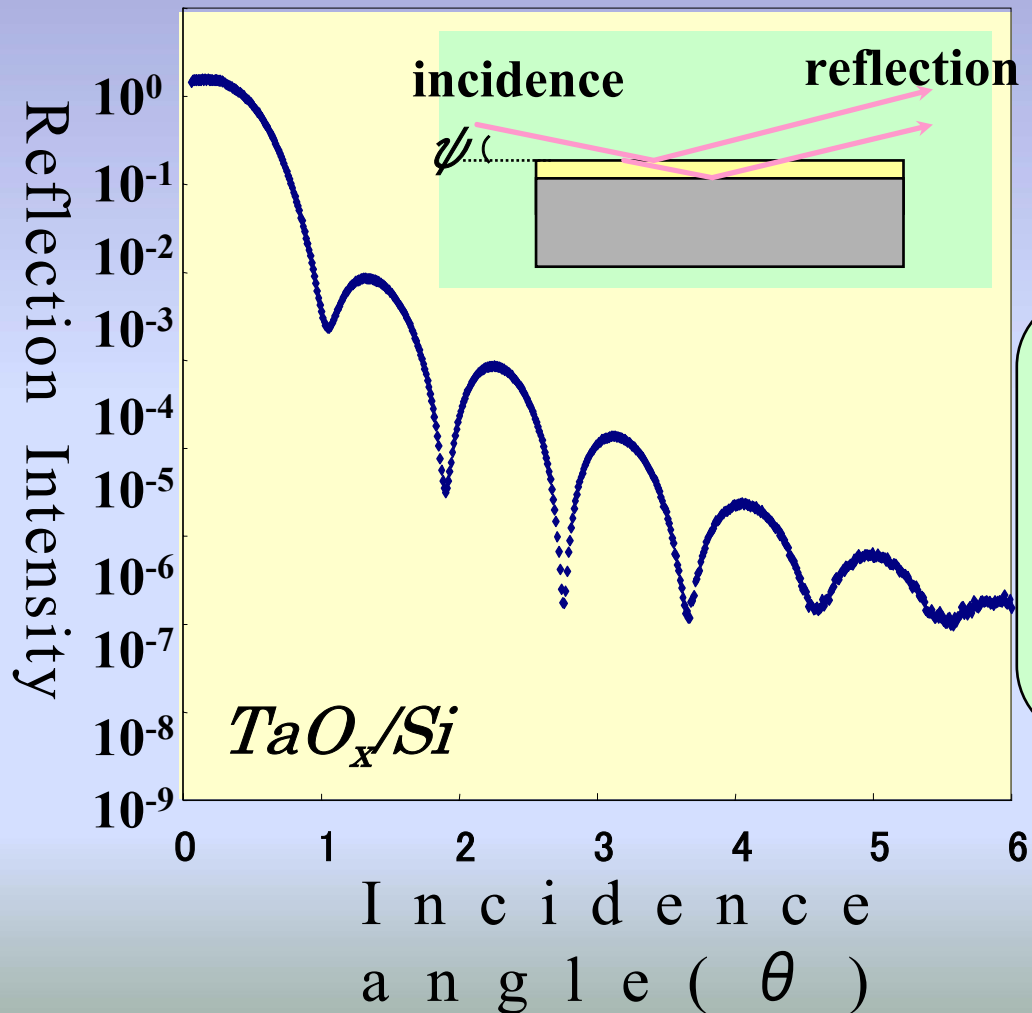
key points for R&D: gate & lines



Grazing incident x-ray reflection and diffraction



X-ray reflectivity analysis

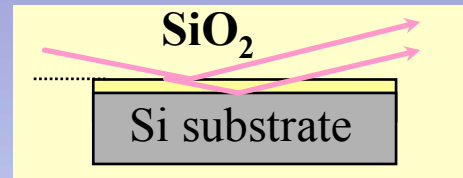
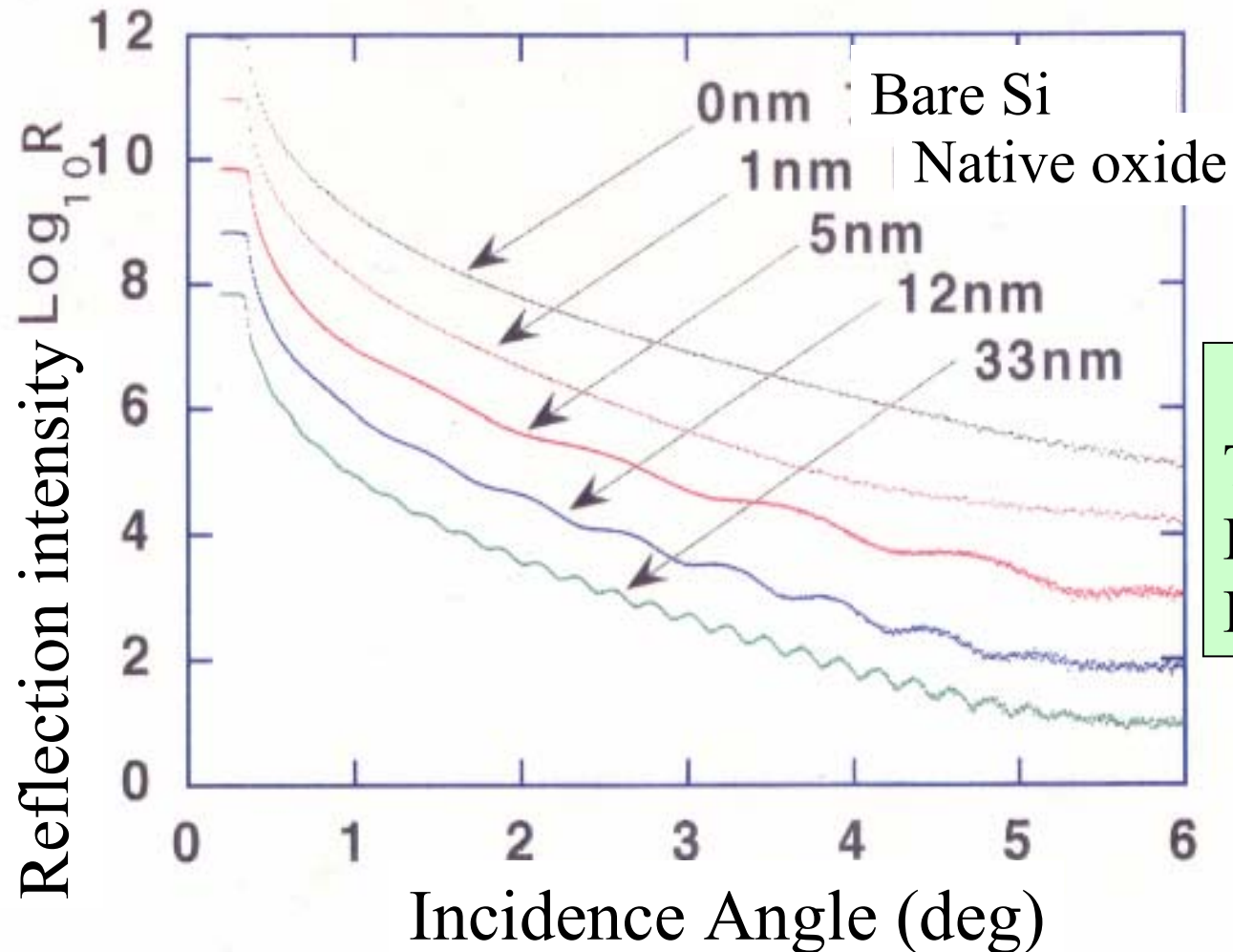


Information obtained by reflectivity analysis

Reflectivity	Information
• Period	⇒ Thickness
• Amplitude	⇒ Density
• Damping	⇒ Roughness

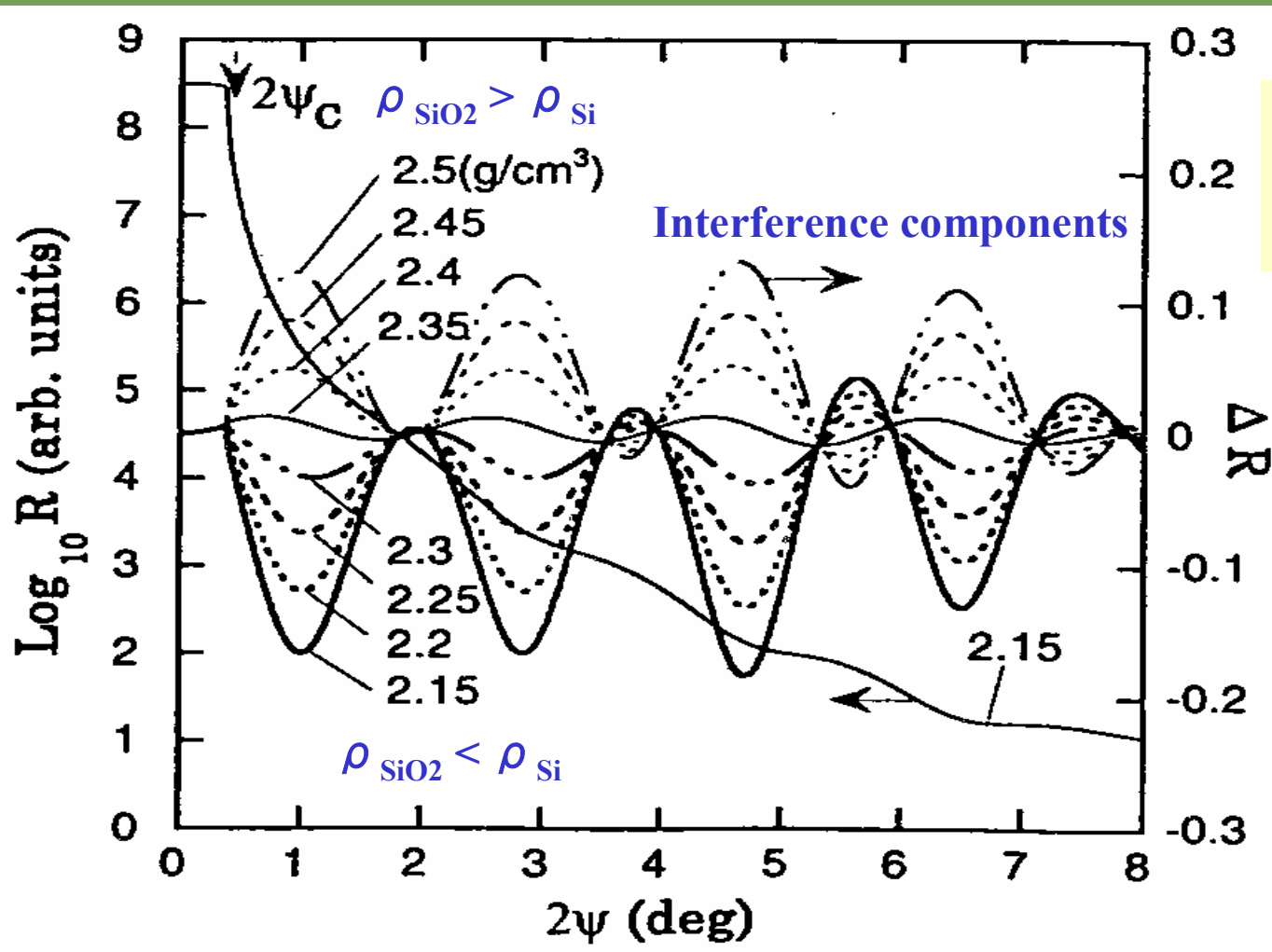


X-ray reflectivity profiles of oxide films on silicon substrates



Accuracy
 Thickness : 0.01nm
 Density : 0.01g/cm³
 Roughness : 0.02nm

X-ray reflectivity profile and interference components (calculation)



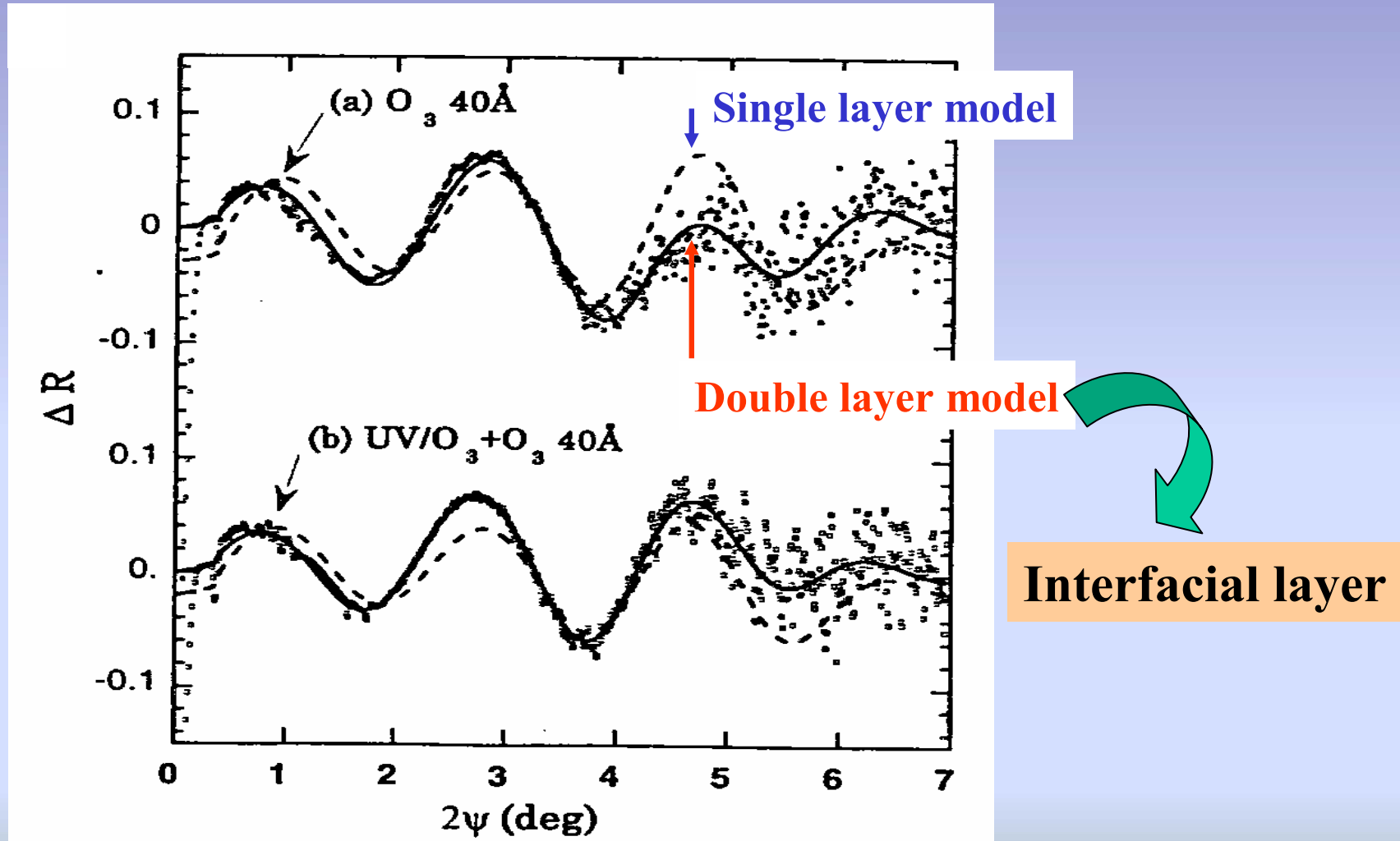
SiO₂ on Si
thickness: 4nm
 $\rho_{\text{Si}} = 2.33 \text{ g/cm}^3$

$\Delta R = \log_{10}(R/R_{\text{ave}})$
 R_{ave} : reference

Subtraction technique of the interference component derive easy analysis.



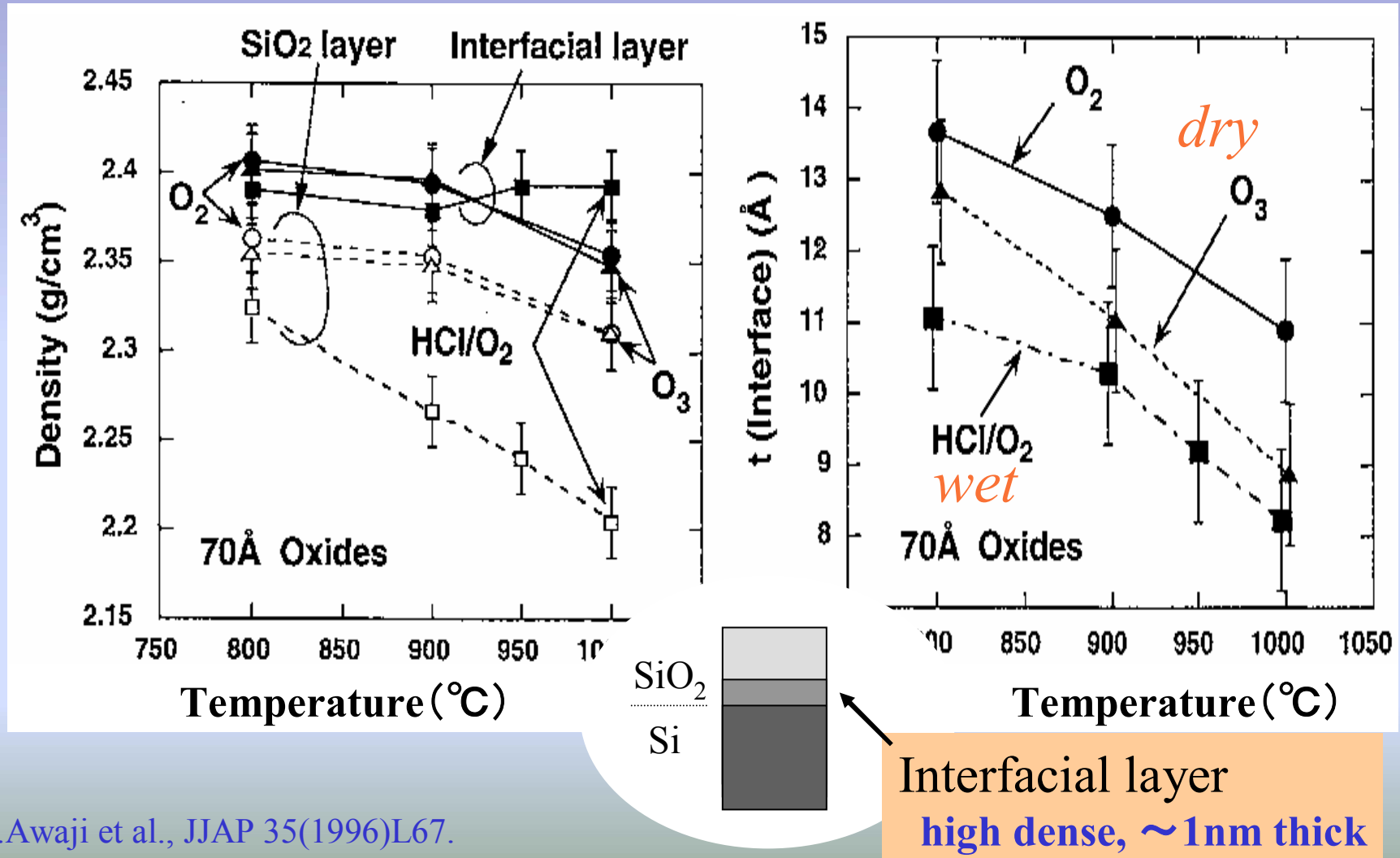
Analysis with the interference component



4nm thin SiO_2 on Si fabricated by thermal oxidation

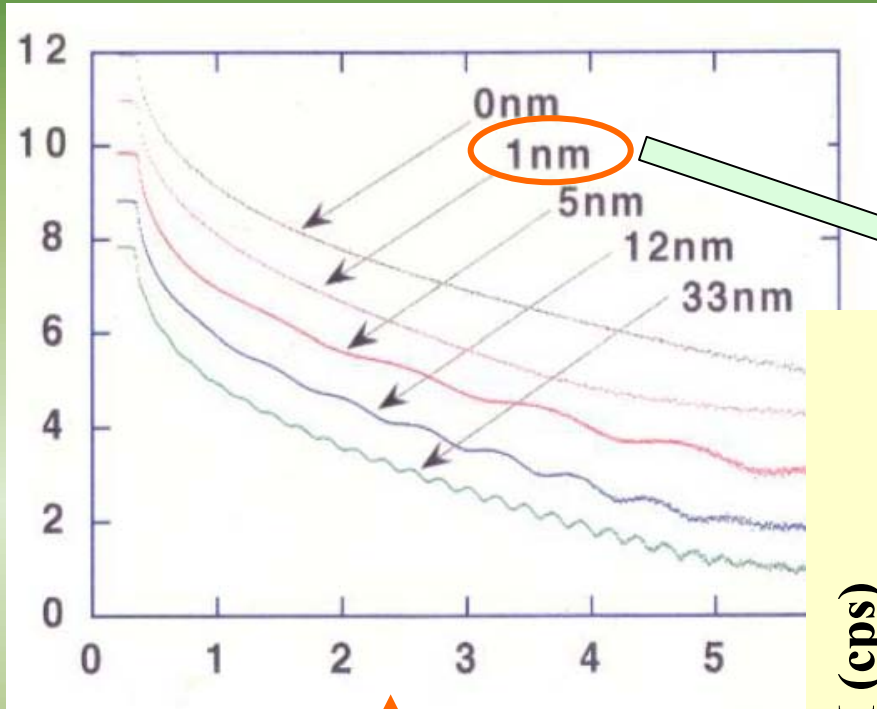


Generation of high dense interfacial layer on thermal oxidation process

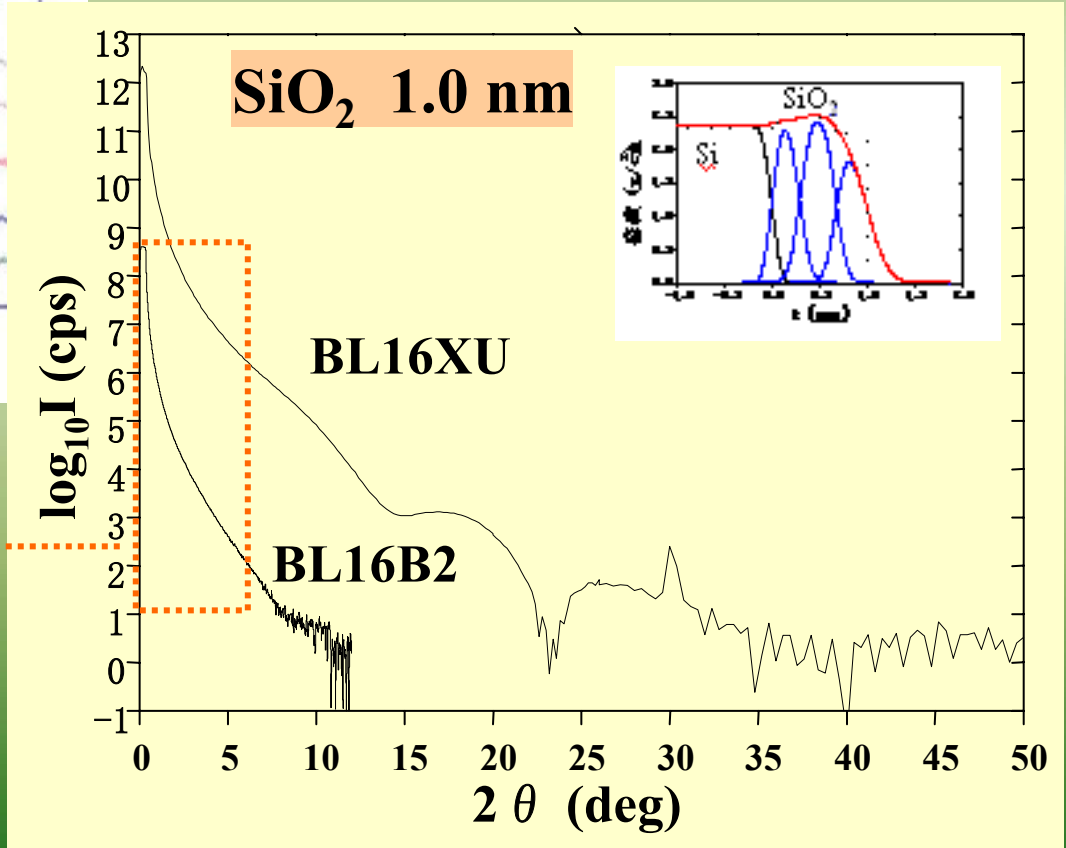




Development of measurement technique



Accurate evaluation of ultra-thin films



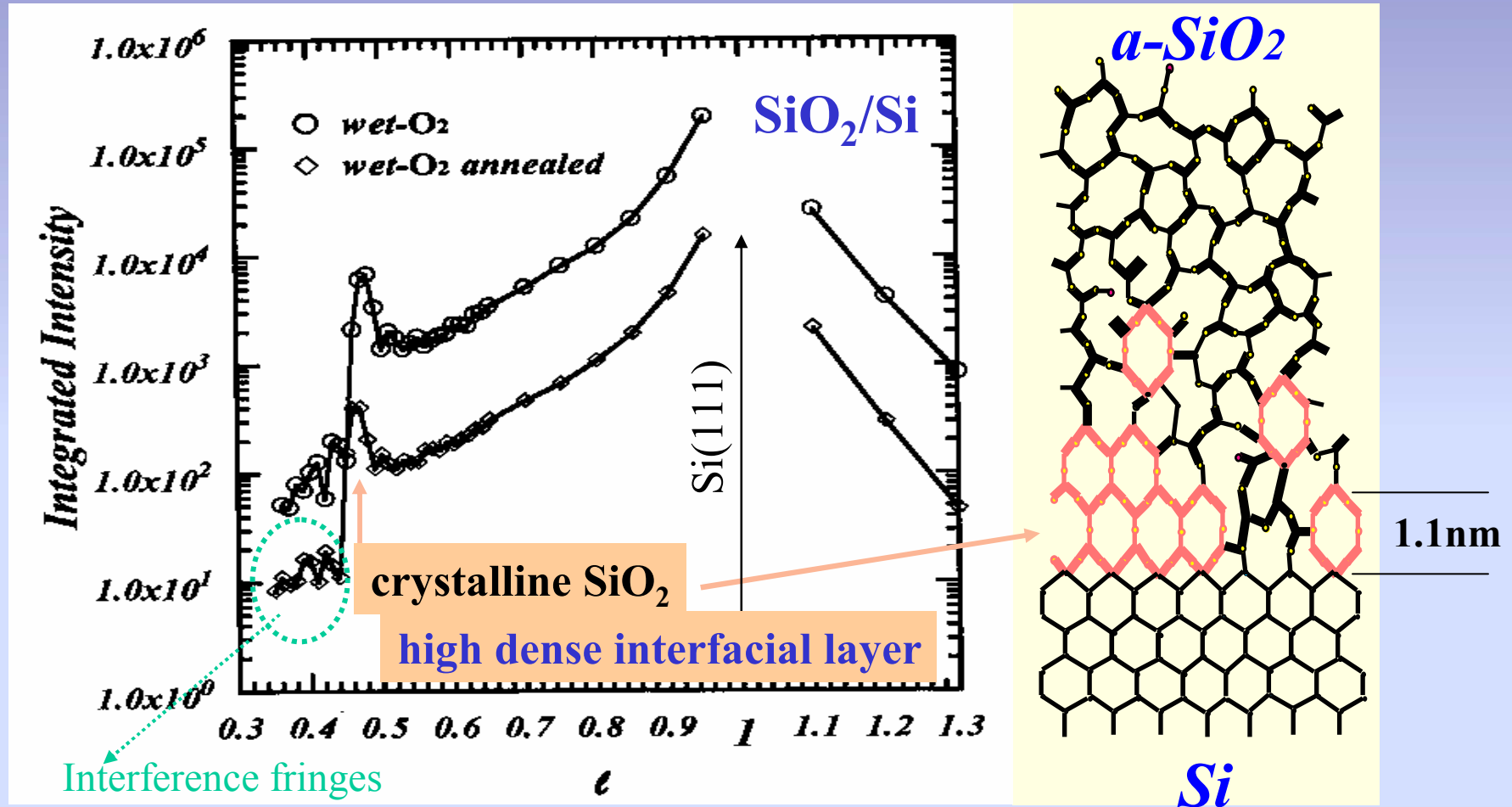
Same region

BL16XU:undulator beamline
BL16B2:bending magnet beamline

N.Awaji in Fujitsu Labs.



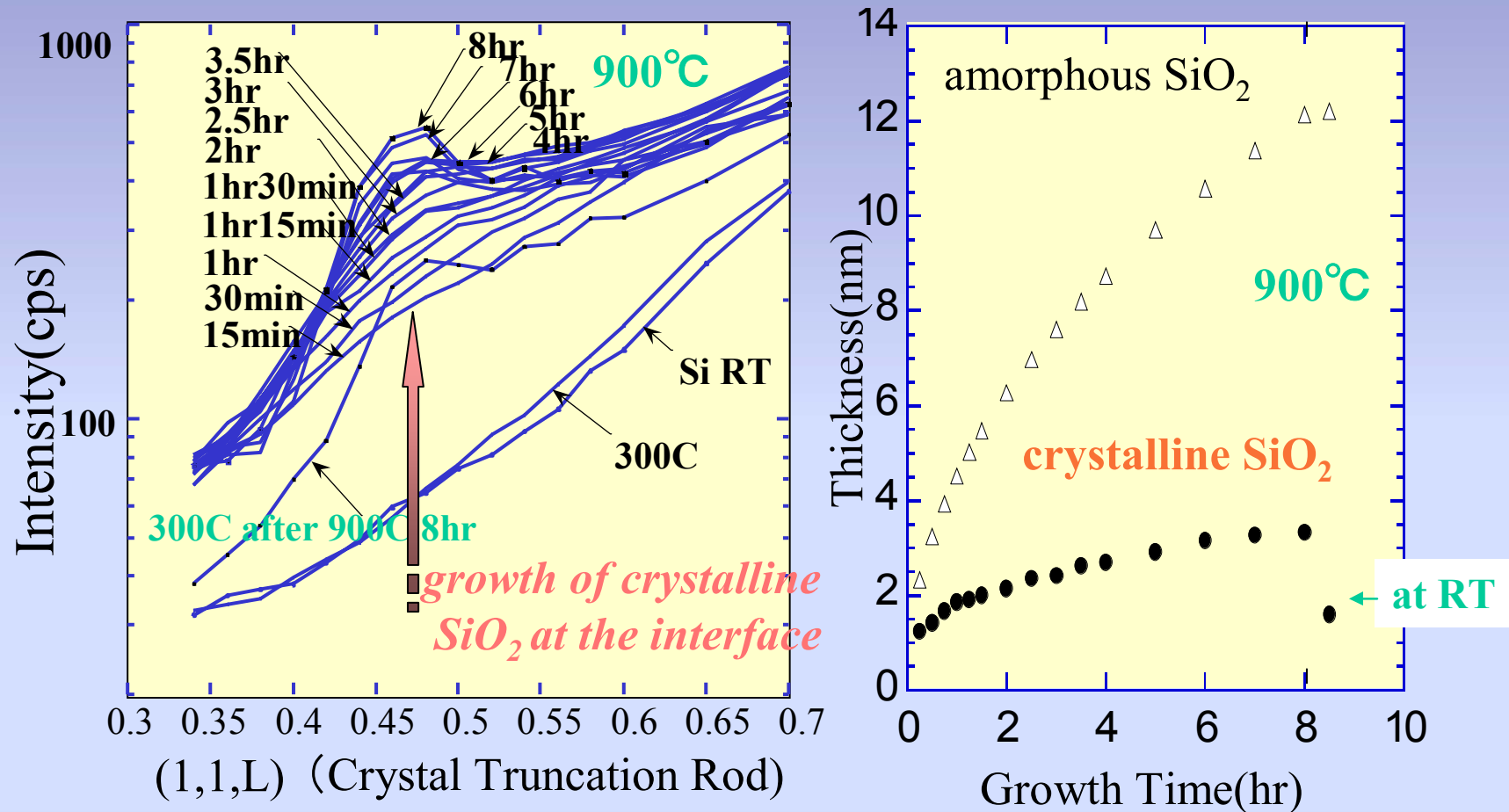
Observation of crystalline SiO₂ in thermal oxides



X-ray Crystal Truncation Rod Scattering



In-situ observation of CTR scattering during thermal oxidation

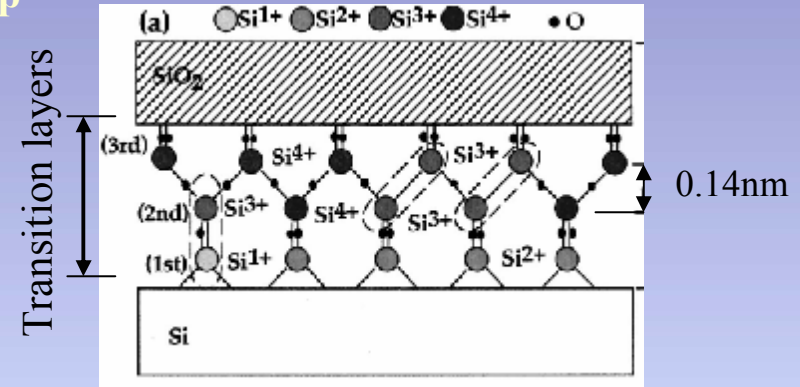
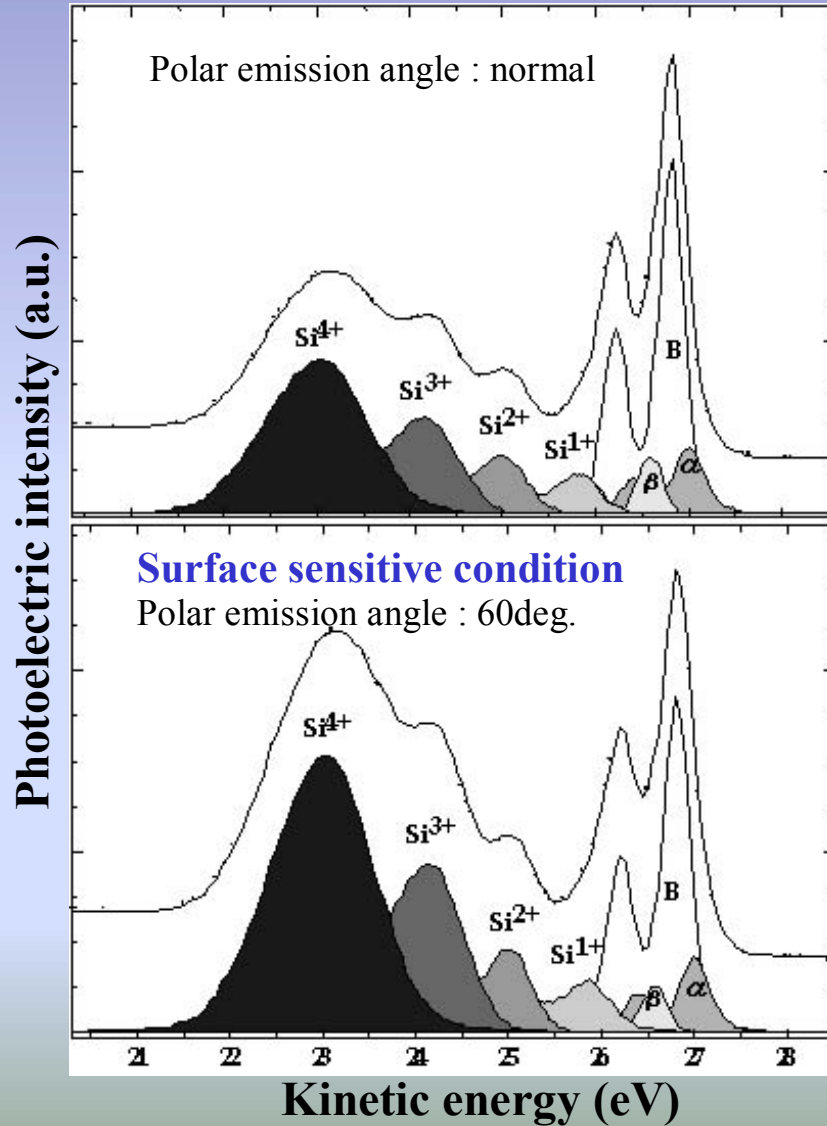


interface layer = oxidation front : ~ 1 nm at RT
 fundamental phenomena on thermal oxidation



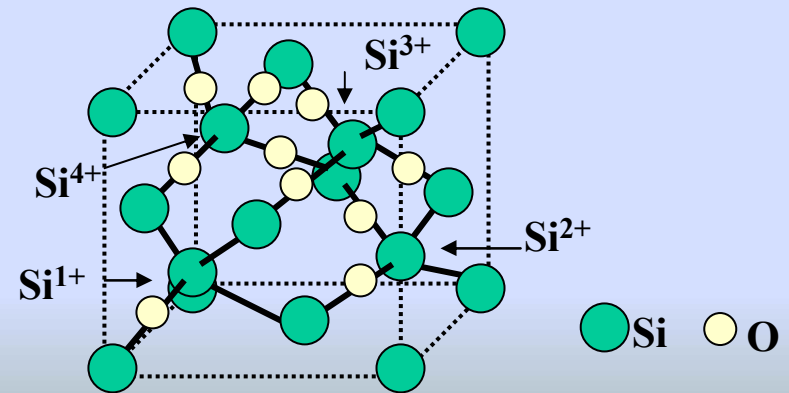
Analysis of Si-oxidation by XPS

SiO₂ (~0.6 nm) on Si(001)2x1 $h\nu = 130\text{eV}$ Si2p

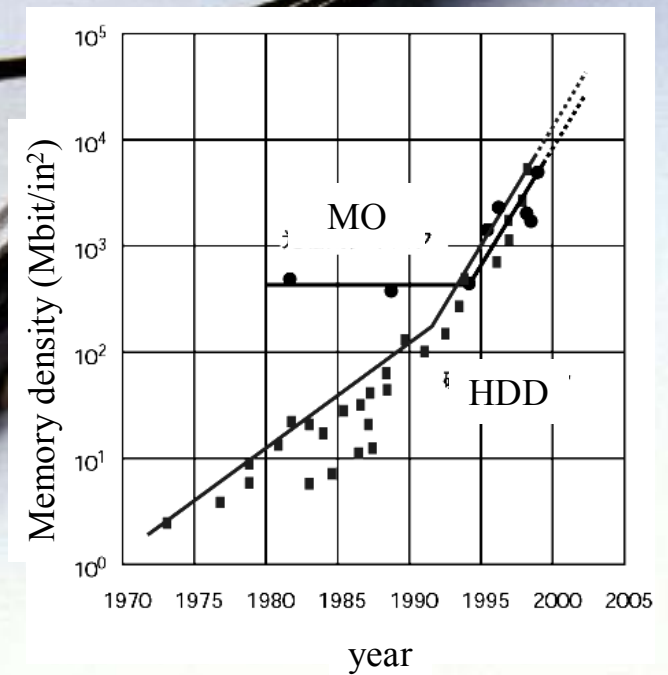
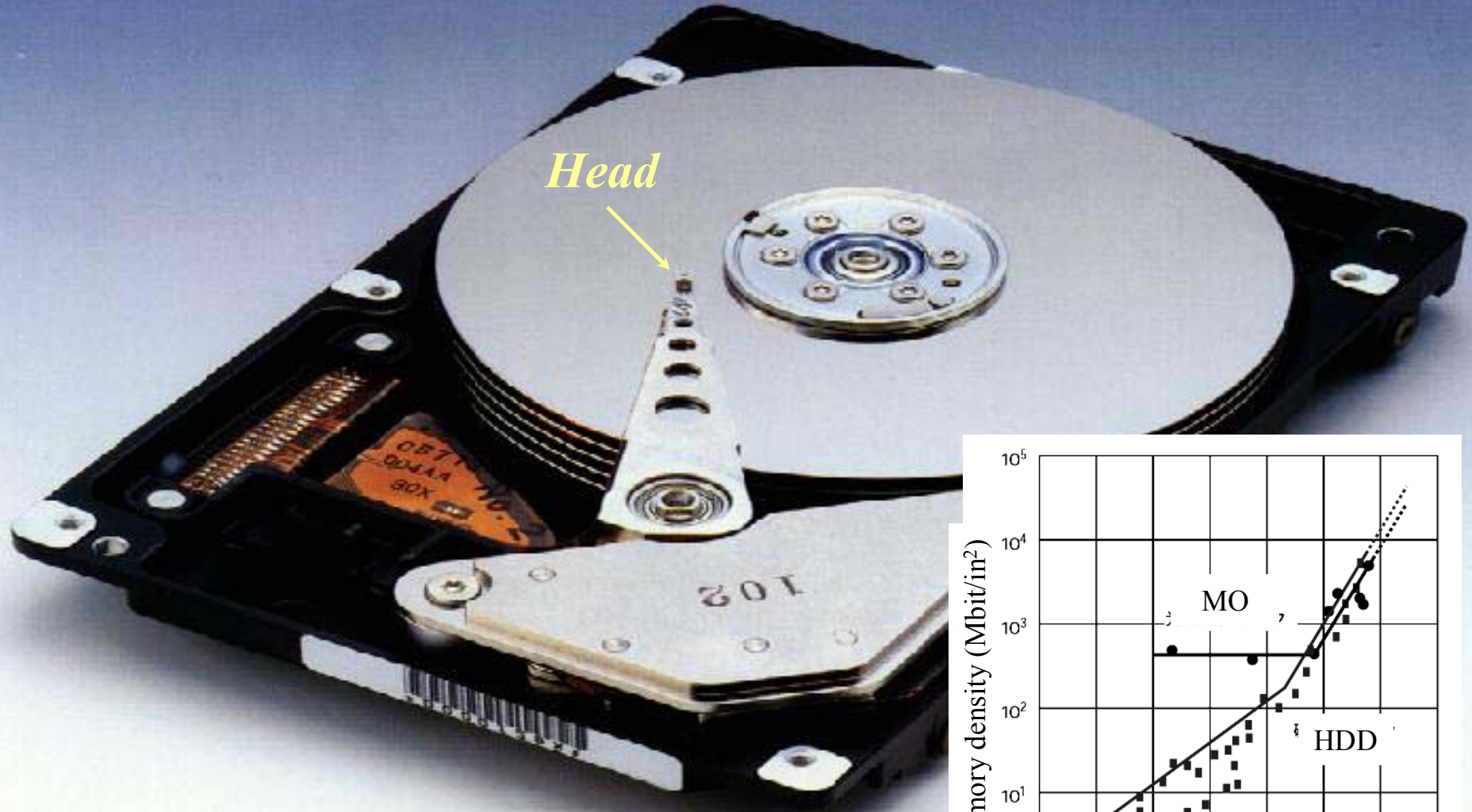


Transition layer model

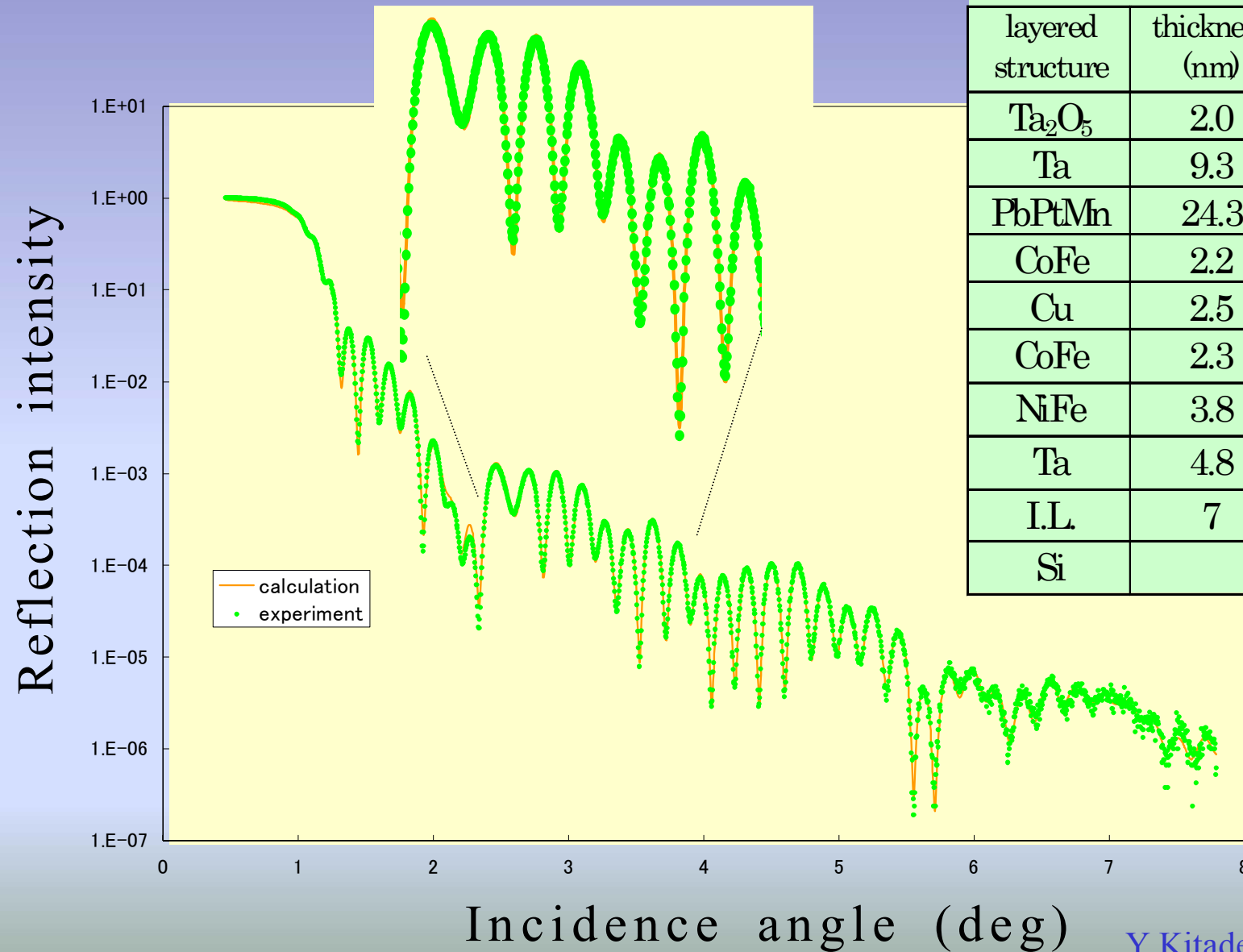
- 3rd Si³⁺/Si⁴⁺ (Si³⁺ << Si⁴⁺)
- 2nd Si³⁺/Si⁴⁺ (Si³⁺ < Si⁴⁺)
- 1st Si¹⁺/Si²⁺ (Si¹⁺ < Si²⁺)



Hard Disk Drive



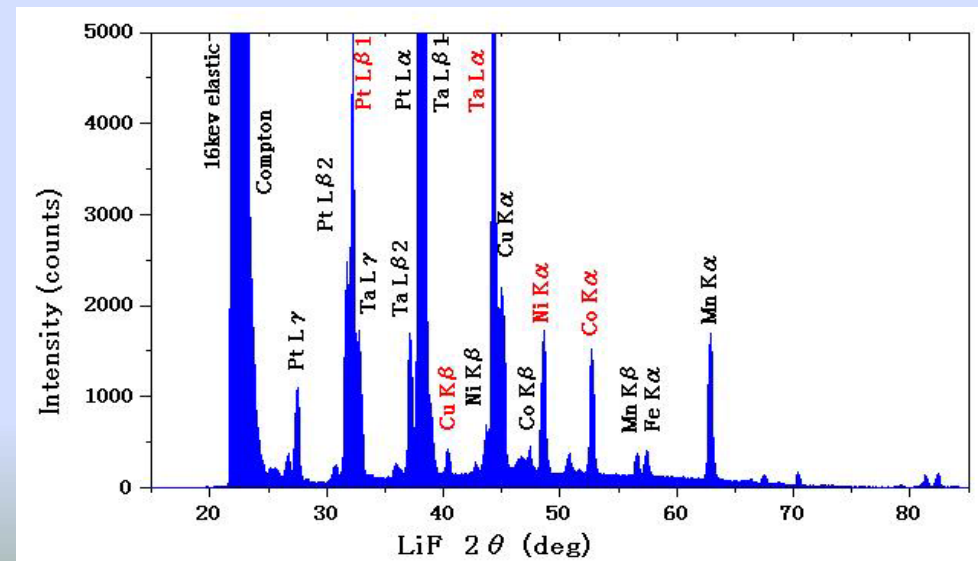
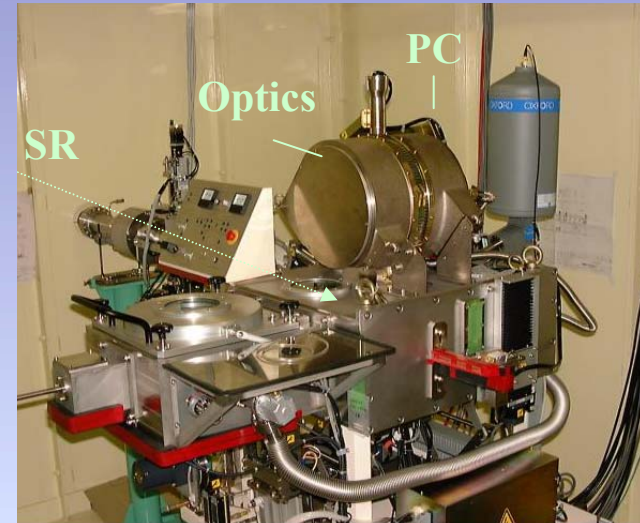
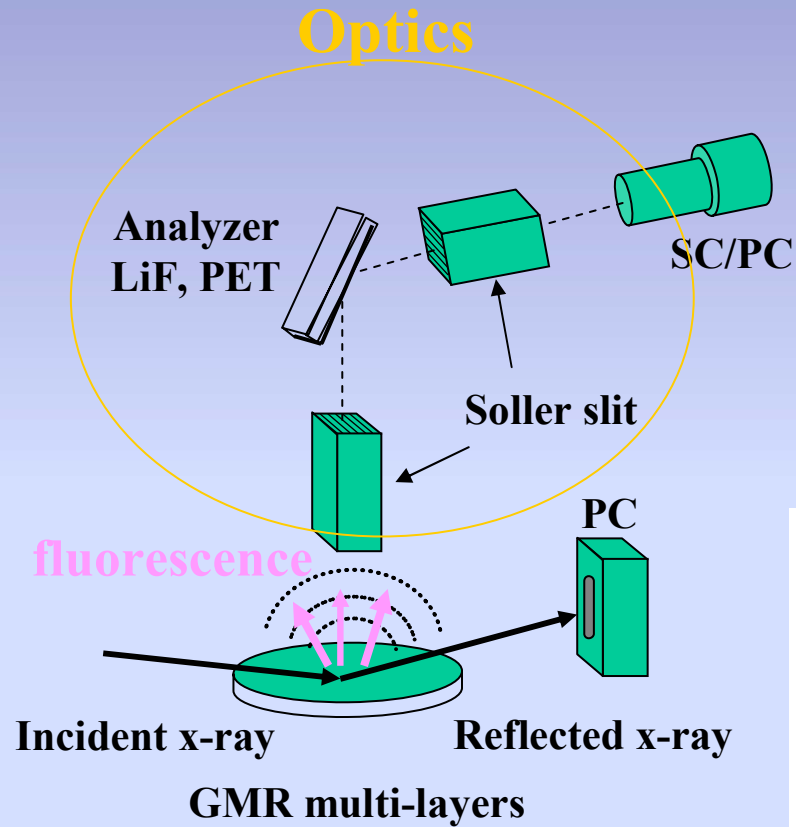
X-ray reflectivity analysis of multi-layers



layered structure	thickness (nm)	roughness (nm)
Ta ₂ O ₅	2.0	0.6
Ta	9.3	0.5
PbPtMn	24.3	0.5
CoFe	2.2	0.4
Cu	2.5	0.5
CoFe	2.3	0.4
NiFe	3.8	0.3
Ta	4.8	0.4
I.L.	7	0.2
Si		0.3



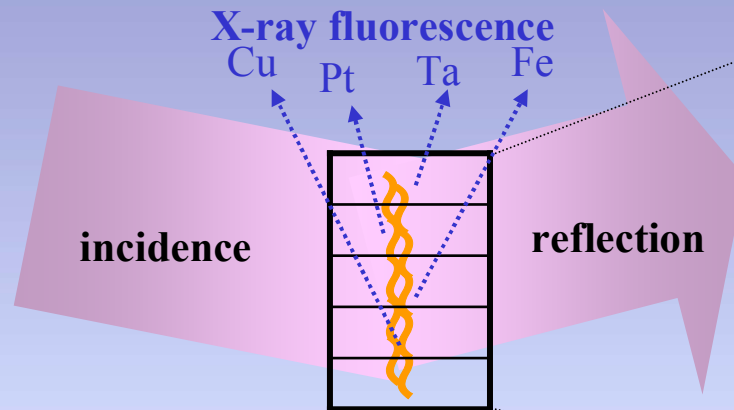
Wavelength dispersive X-ray fluorescence



Fluorescence spectra from spin-valve multi-layers with grazing incidence

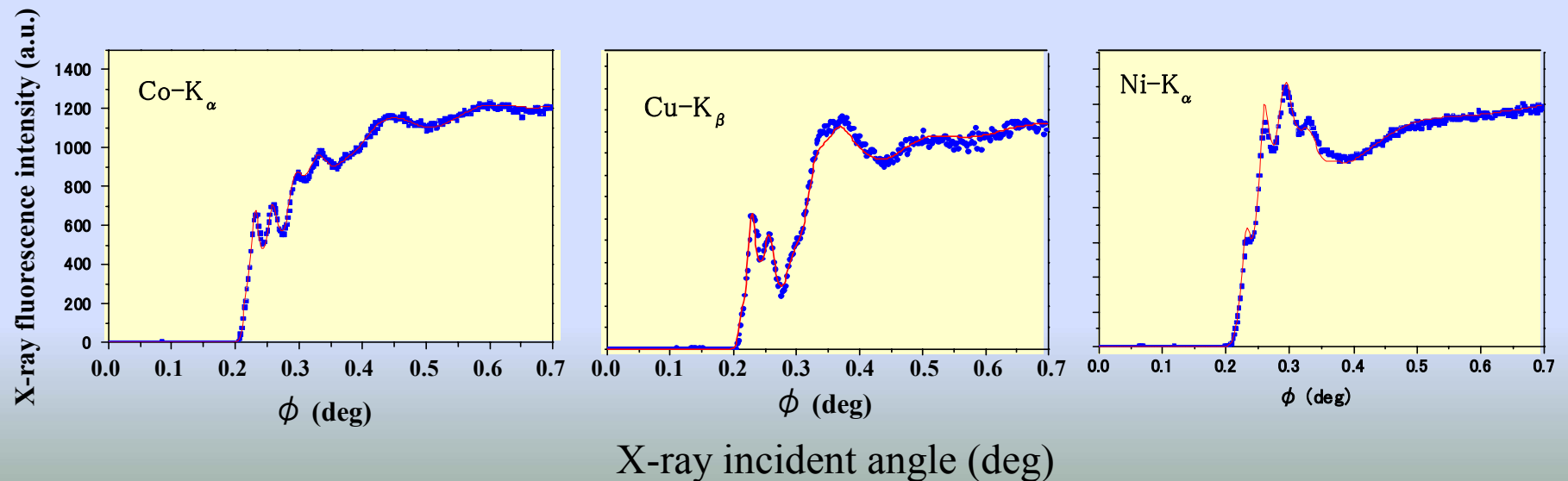


Grazing Incidence X-ray Fluorescence Technique

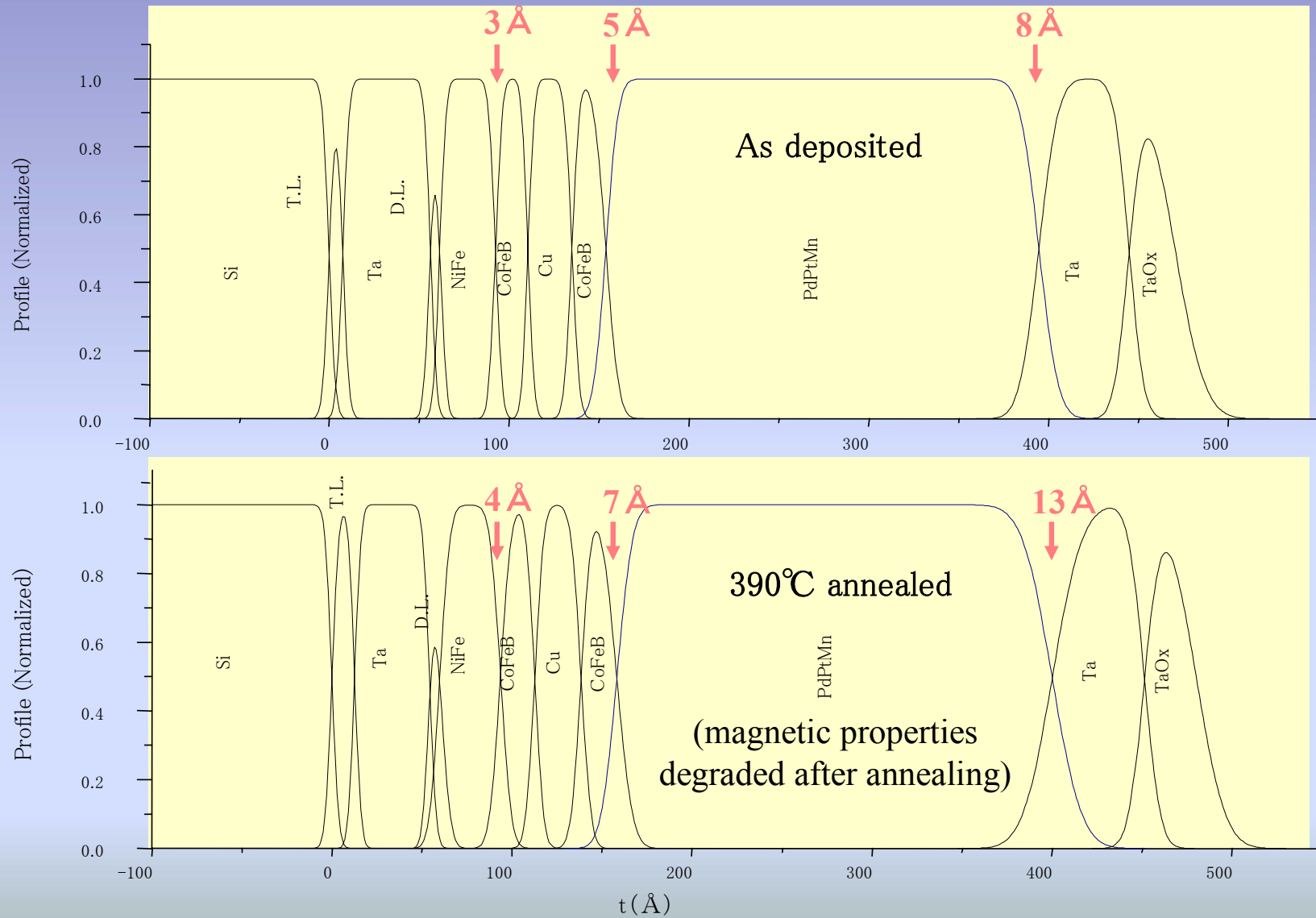


Standing wave is induced into multi-layers

Ta ₂ O ₅
Ta
PdPtMn
CoFe
Cu
CoFe
NiFe
Ta
T.L.
Si substrate

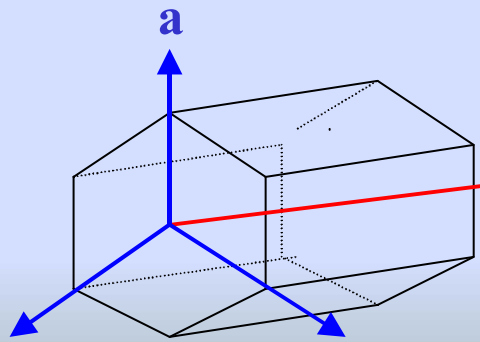
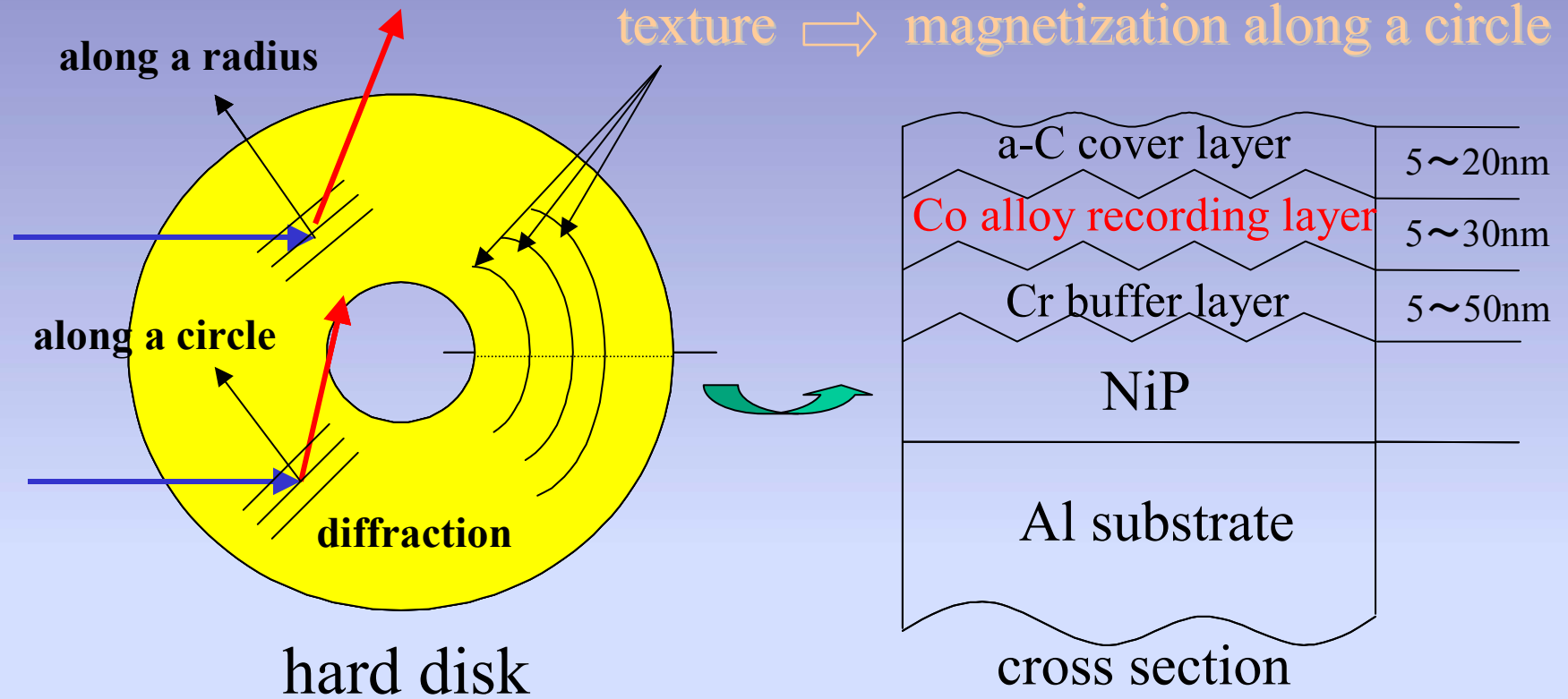


Broadening of the interfaces in GMR multilayers



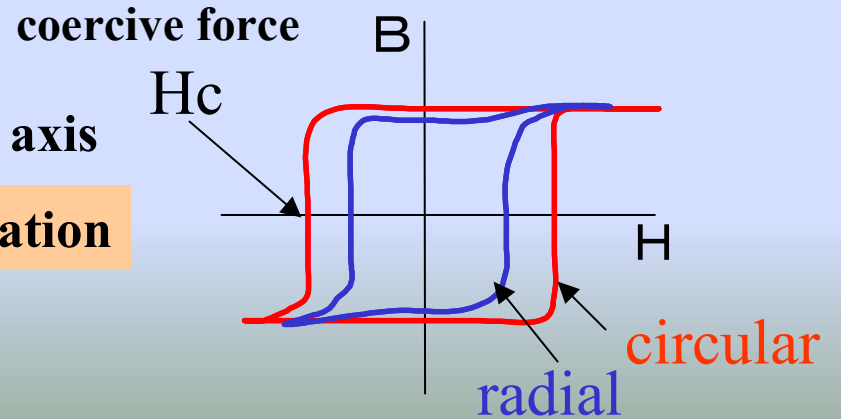
Depth profiles of elements analyzed from GIXF and reflectivity data

record along a circle and in-plane magnetization



control the orientation

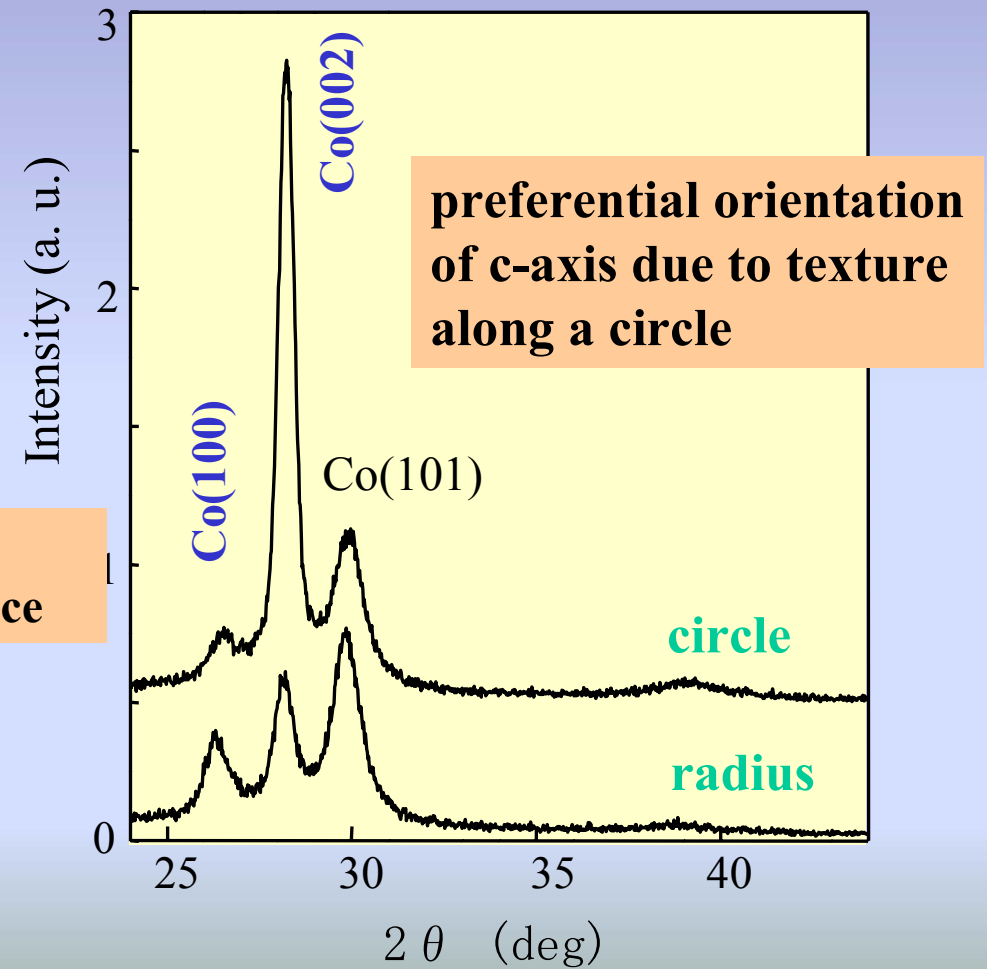
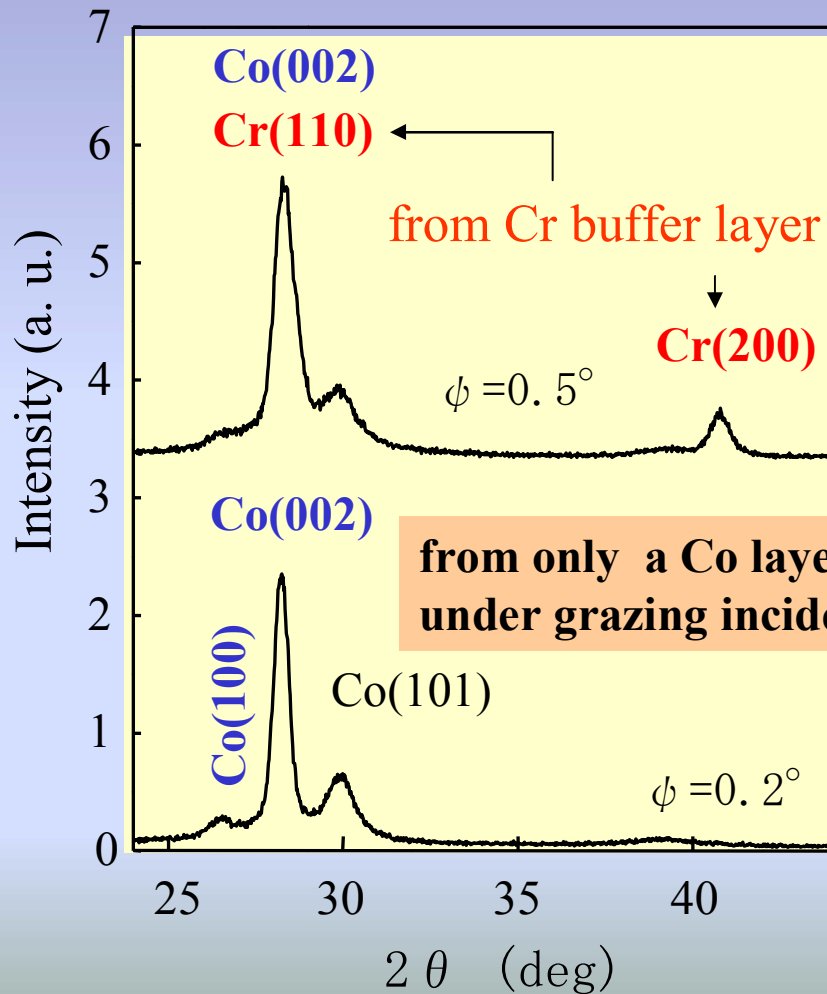
Co alloy : hcp crystal





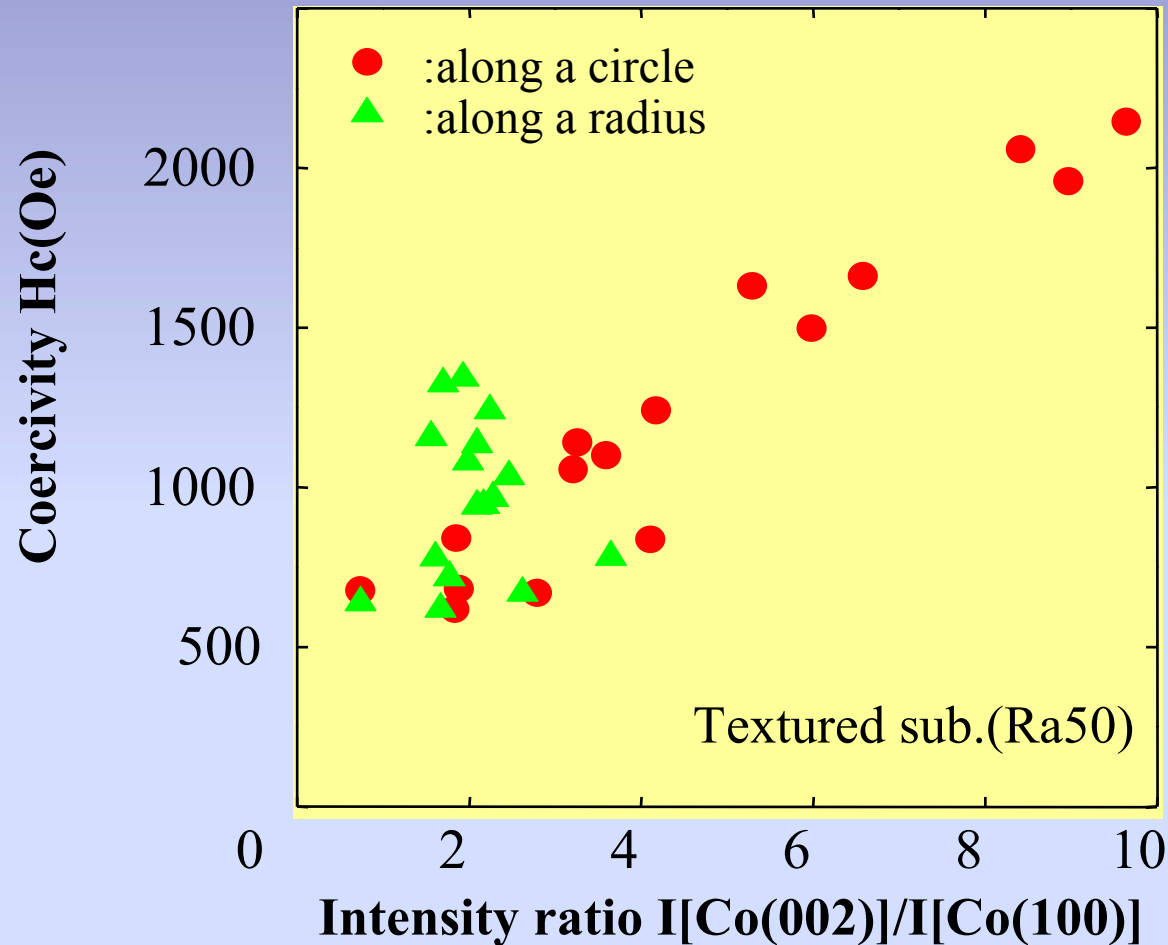
Grazing incidence x-ray diffraction profiles

Textured-Al/NiP/Cr/Co-alloy(20nm)/a-C





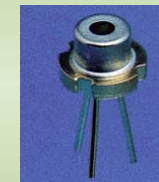
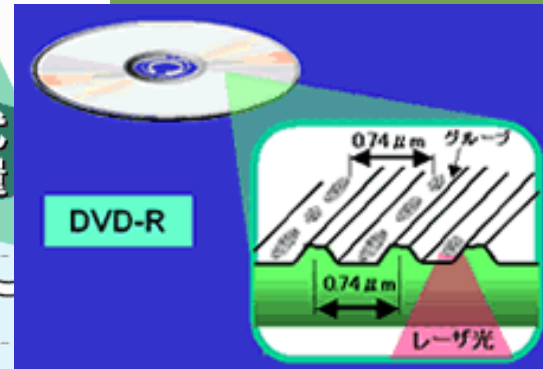
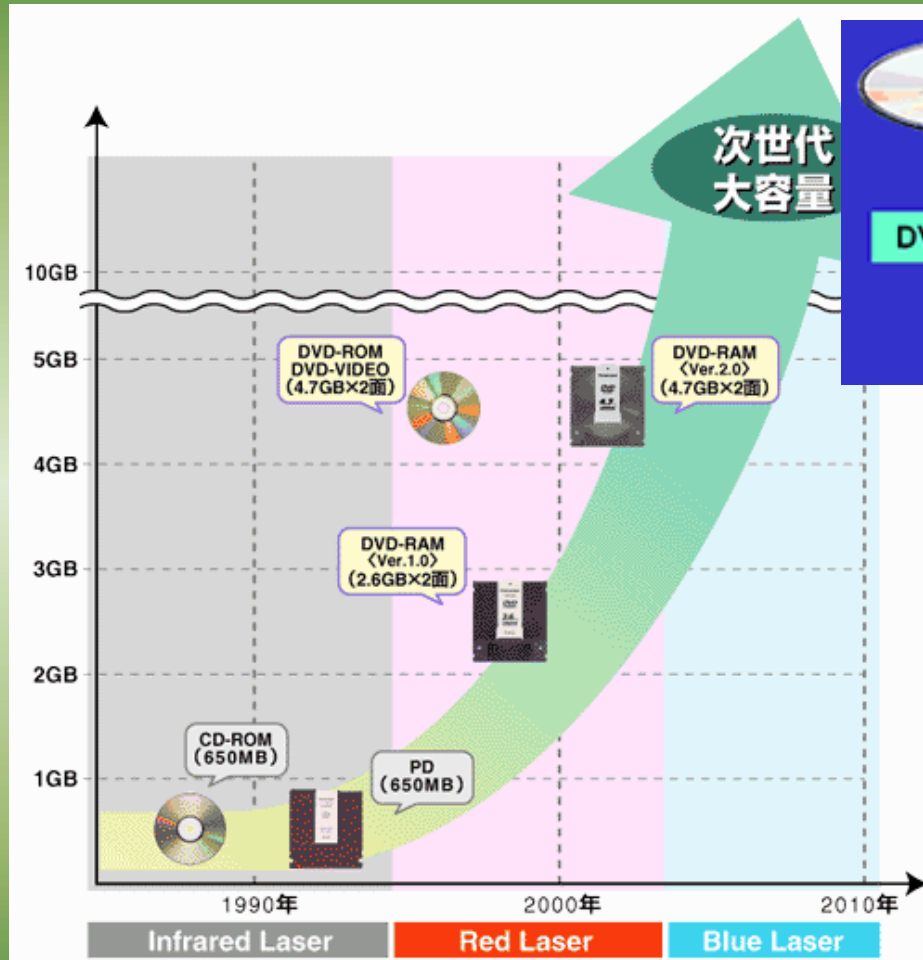
Preferential c-axis orientation dependence of coercive magnetic force



Increase in coercive force due to preferential
c-axis orientation along a circle



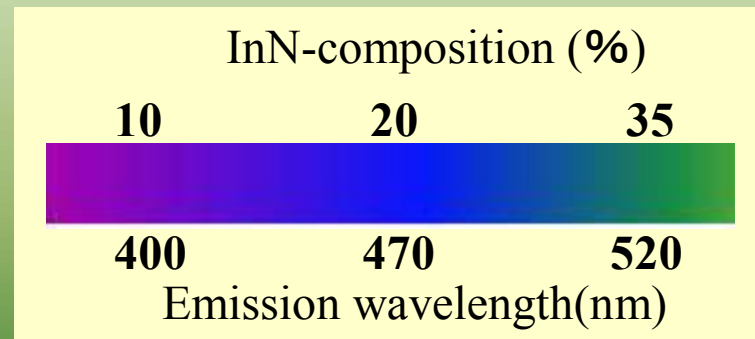
Blue laser for DVD optical storage devices



Red: GaAlAs



Blue: Ga_{1-x}In_xN

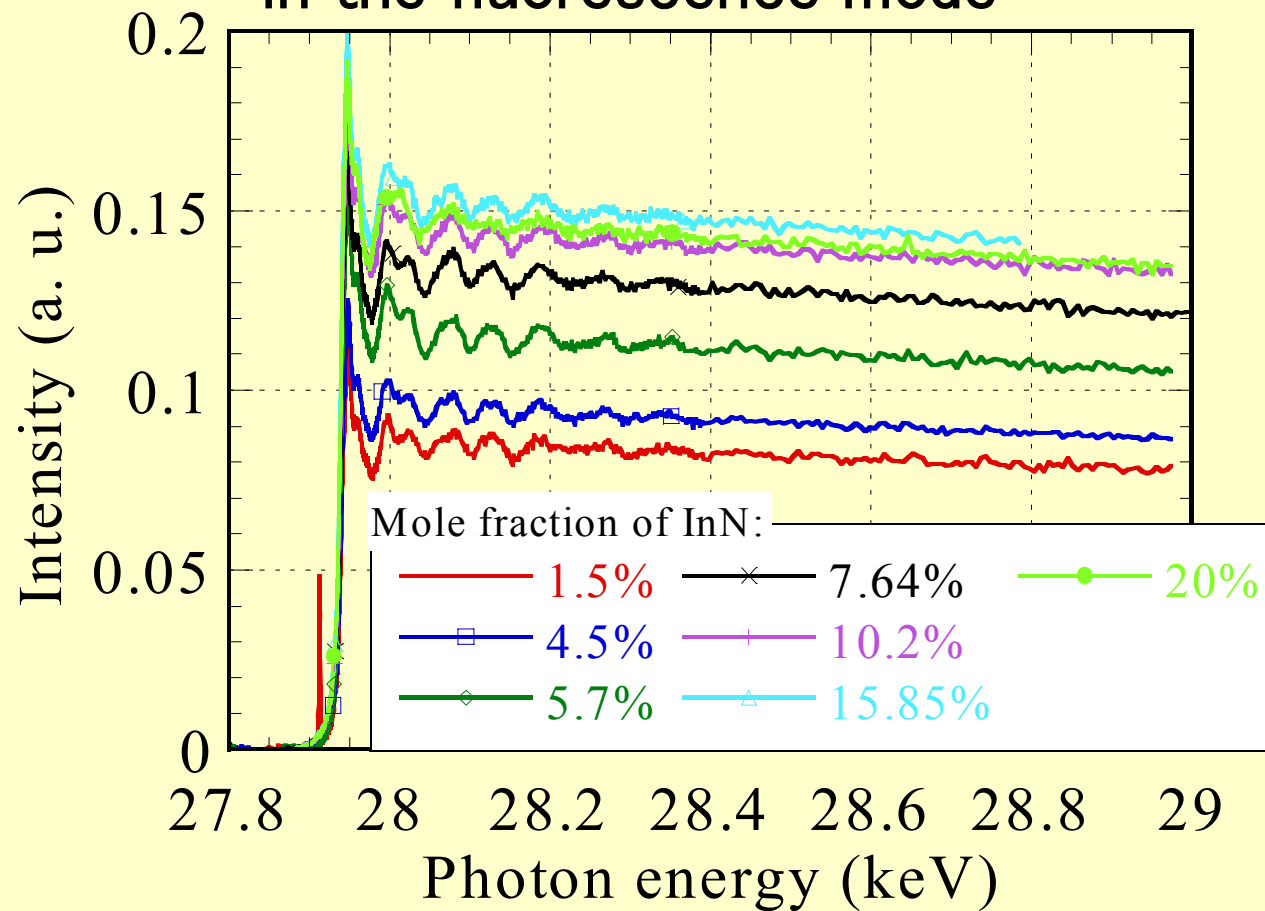


How is local structure in GaInN with low In composition less than 20% which is the critical composition for the phase separation?

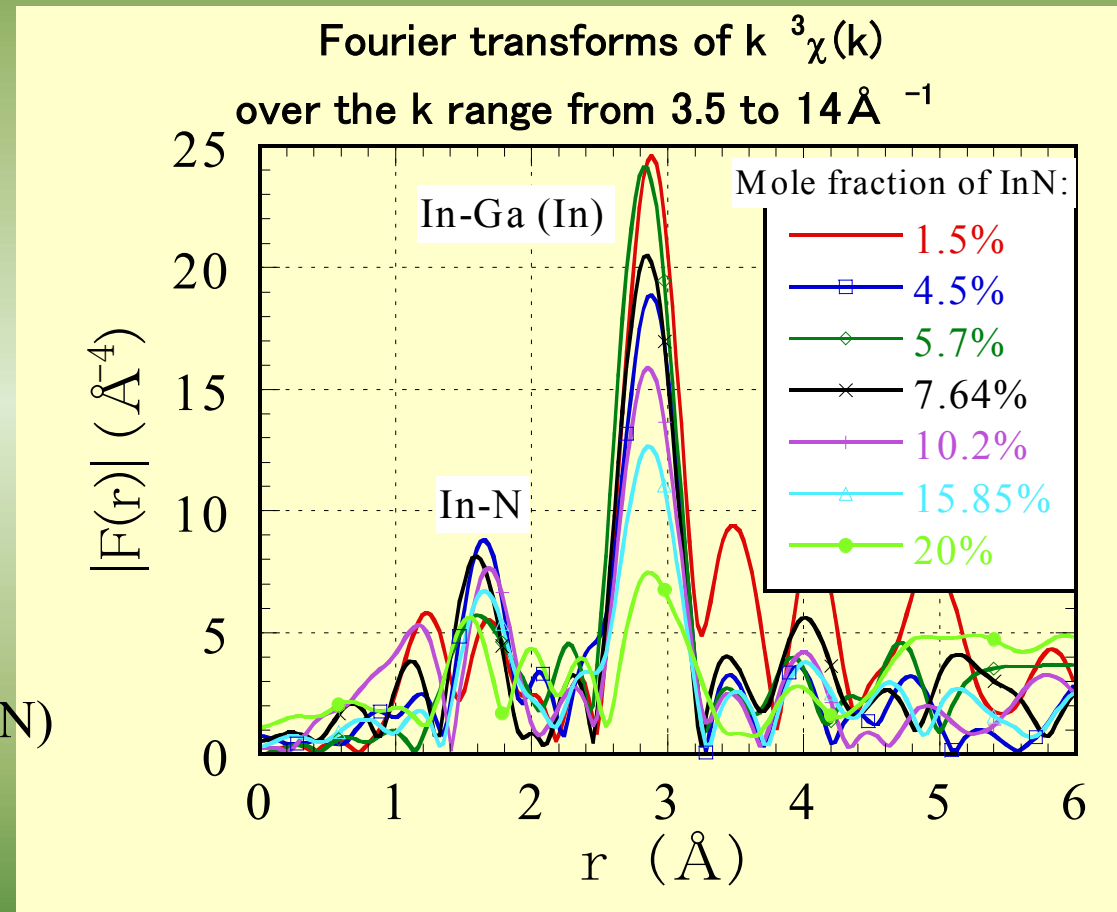
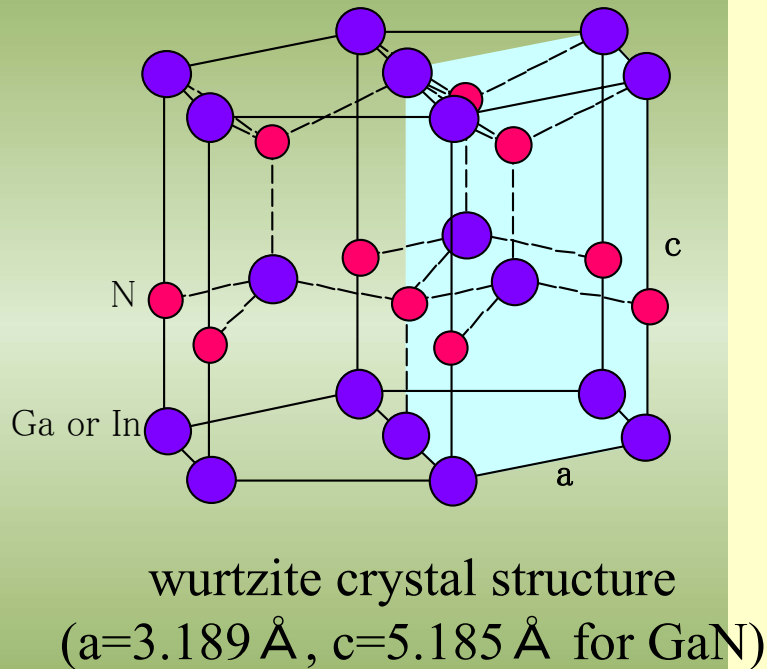


InN composition dependence of GaInN XAFS

XAFS spectra around In K edge measured in the fluorescence mode



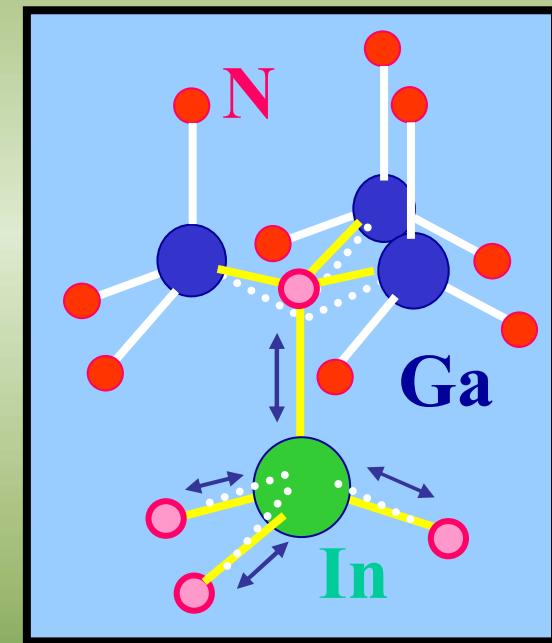
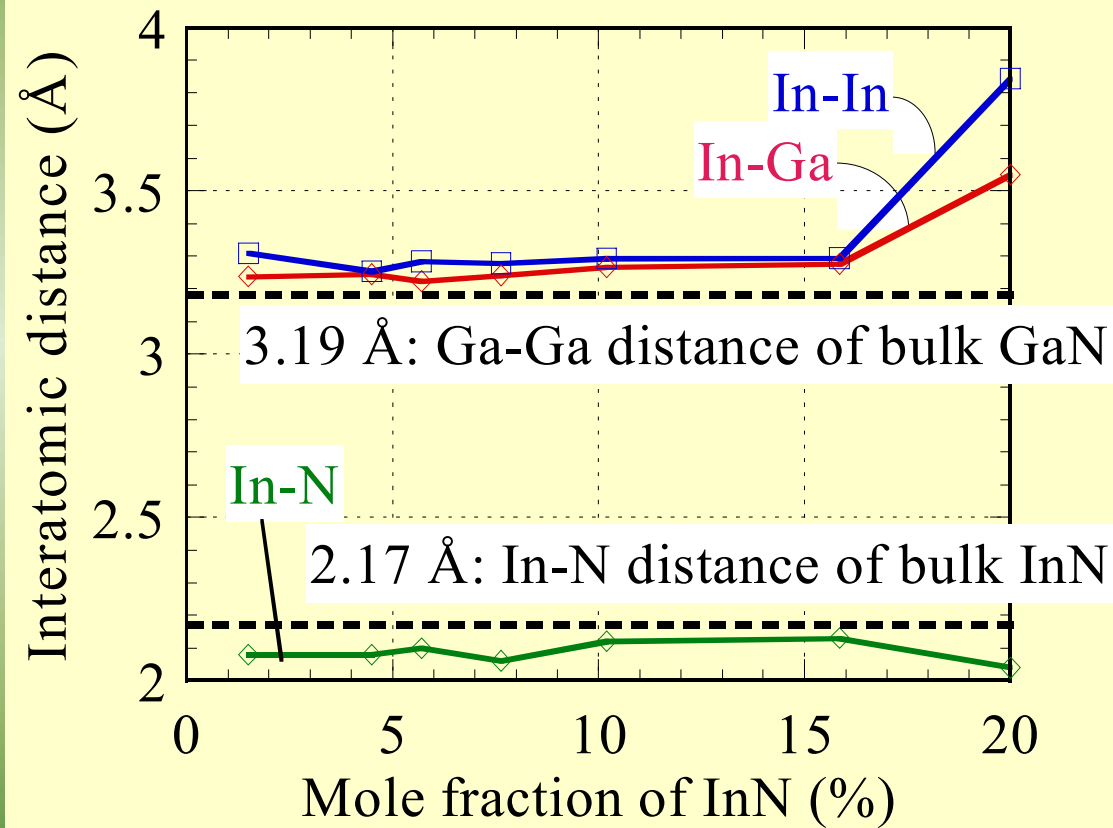
InN composition dependence of radial distribution functions



Monotonic decrease in the second peaks from In-Ga(In)



InN composition dependence of the local structure

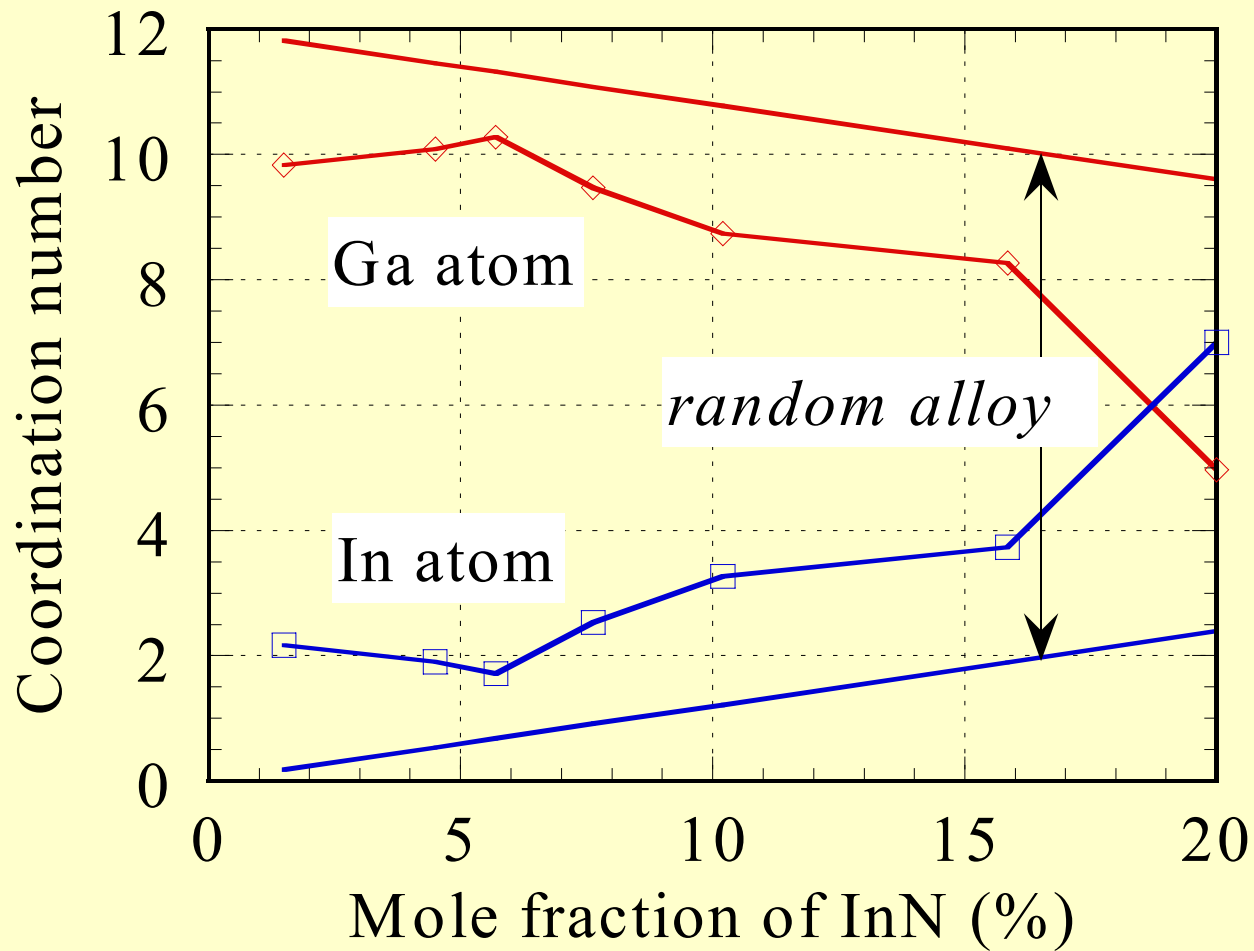


Change of bond angles

InN composition dependence of atomic distances



Deviation from random distribution of Ga and In atoms in GaInN mixed crystal

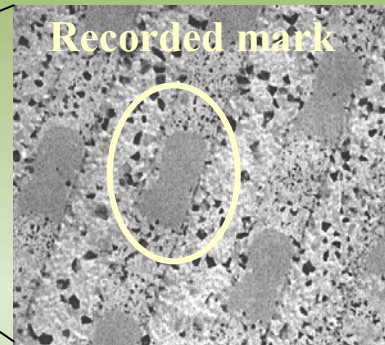
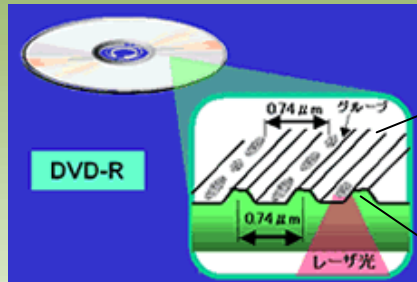


In composition dependence of the 2nd neighbor coordination numbers



Phase transition storage materials for DVD

—Accurate structure analysis with a Debye-Scherrer camera—



Phase transition materials

- AuGeSnTe
- GeSbTe
- AgInSbTe

Record&elimination by laser exposure

- High power→amorphous formation by quenching
- Low power→crystallization by annealing

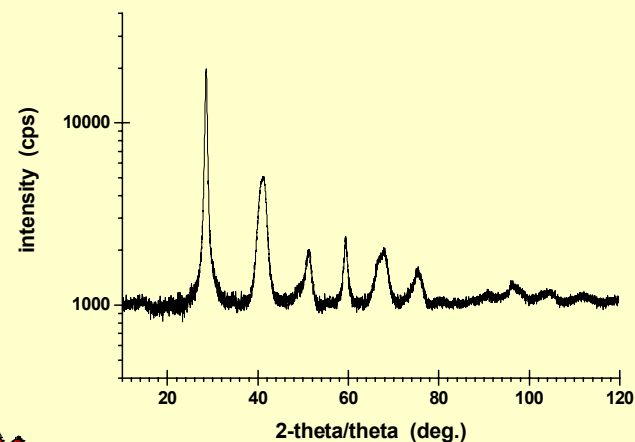
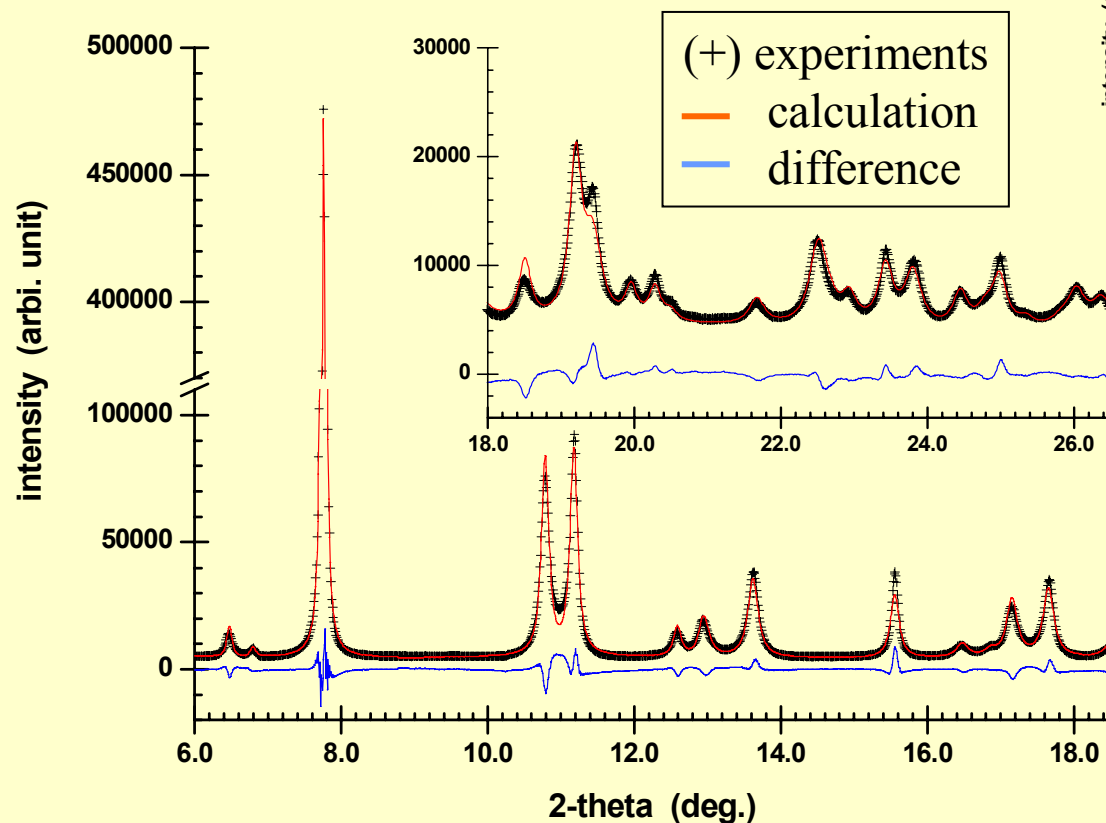
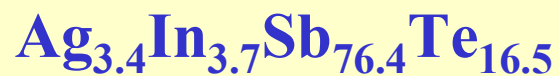


Debye-Scherrer camera

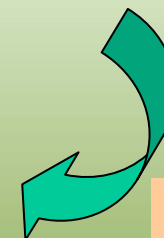
What materials are excellent in high speed record/elimination and reliability



X-ray power diffraction with SR



With a laboratory source



Excellent resolution

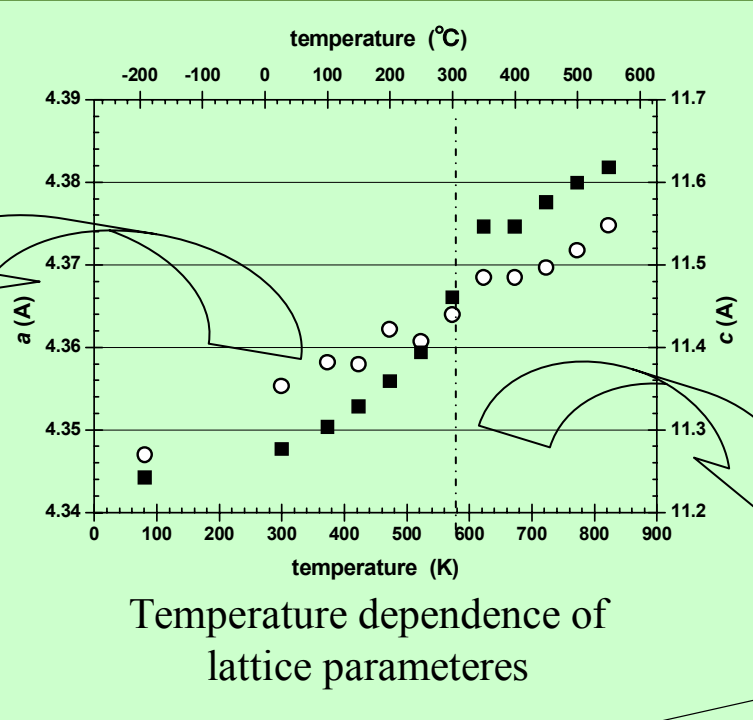
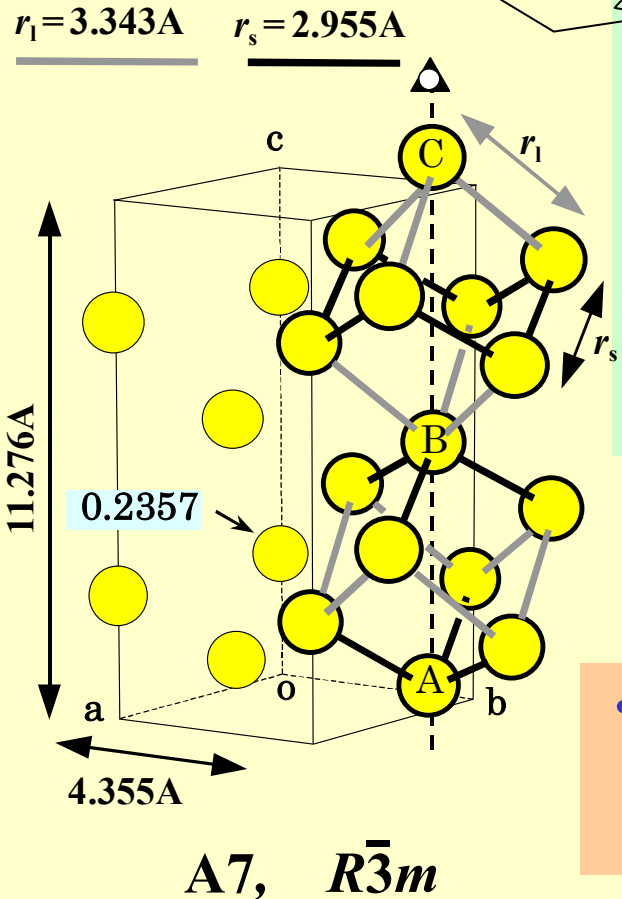
X-ray powder diffraction with SR source



Fine crystalline structure of AgInSbTe

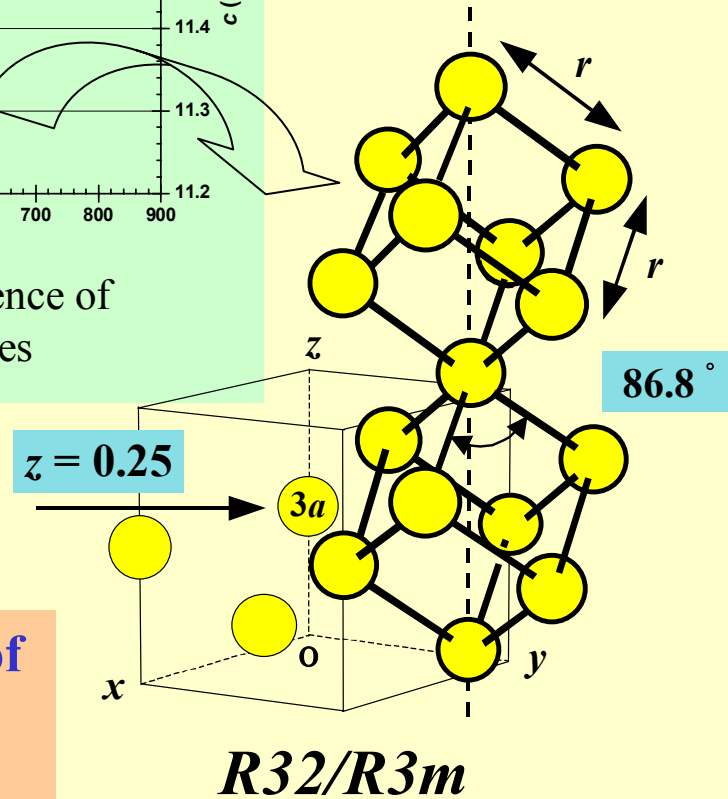


At low temperature



Temperature dependence of lattice parameters

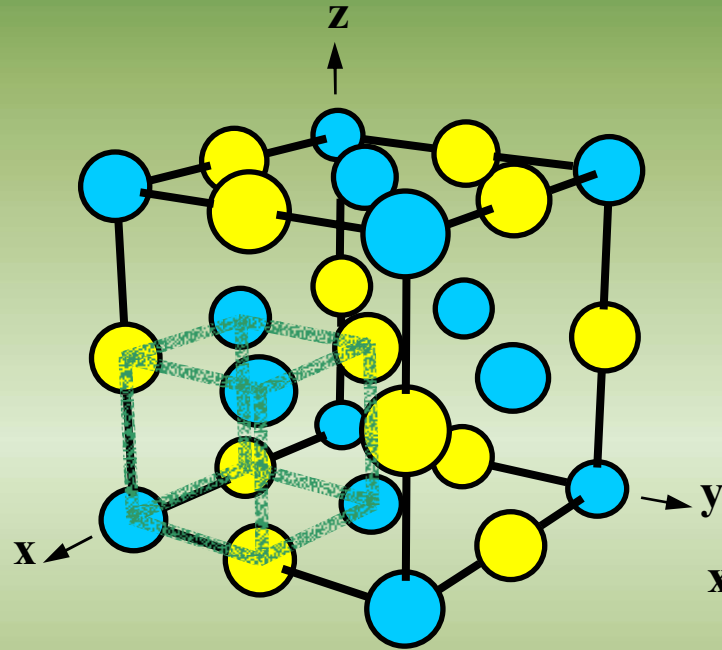
At high temperature



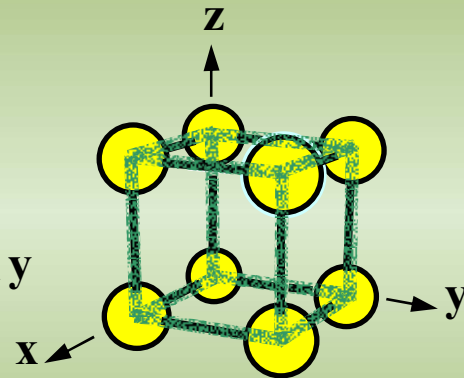
- Random occupancy of Ag, In, Sb, Te
- Simple cubic units



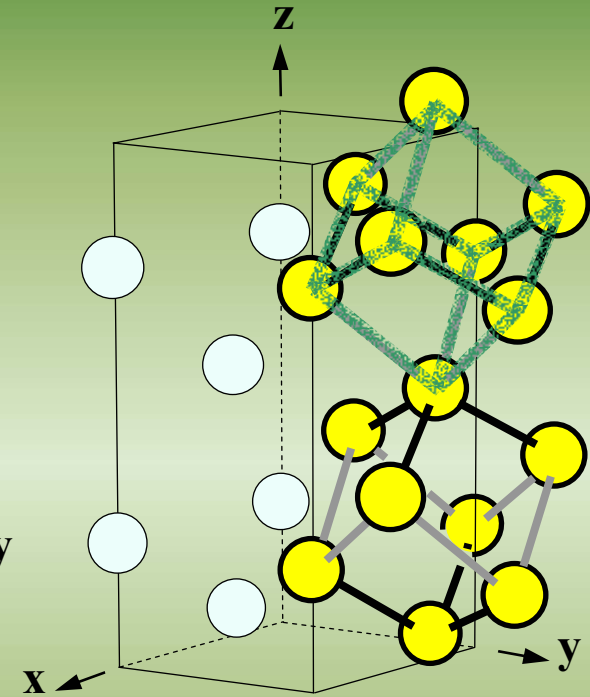
Common properties on three materials



$\text{GeTe-Sb}_2\text{Te}_3$

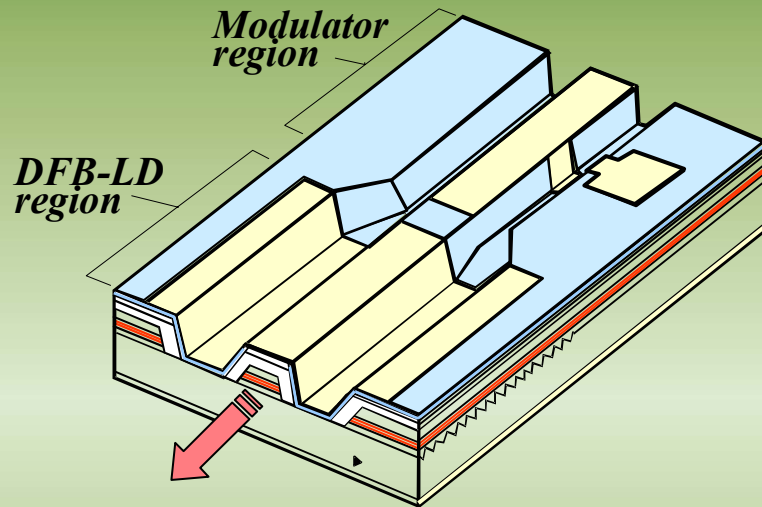


$\text{Au}_{25}\text{Ge}_4\text{Sn}_{11}\text{Te}_{60}$



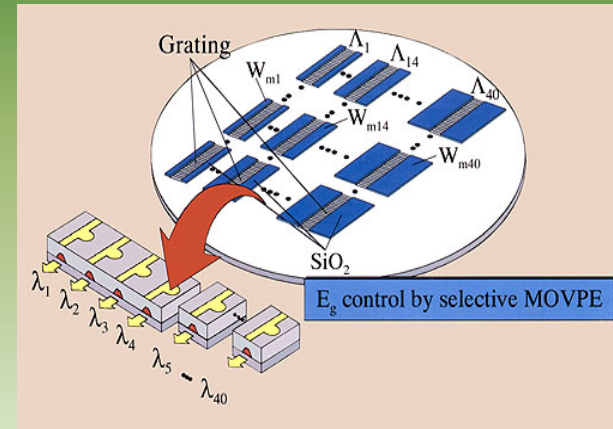
$\text{Ag}_{3.4}\text{In}_{3.7}\text{Sb}_{76.4}\text{Te}_{16.5}$

- Unique crystalline phase
- Poor package : simple cubic, allowance of many vacancies
- Random occupancy of component atoms at lattice sites

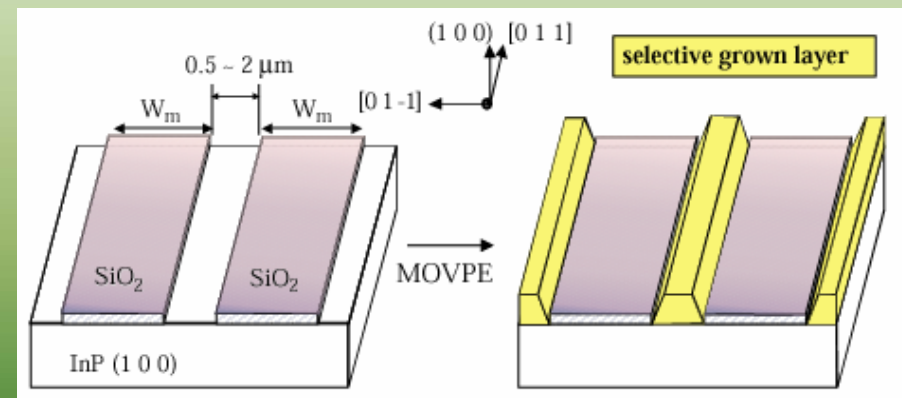


DFB laser diode integrated with wave length modulator for WDM optical communications system

Control of wave length



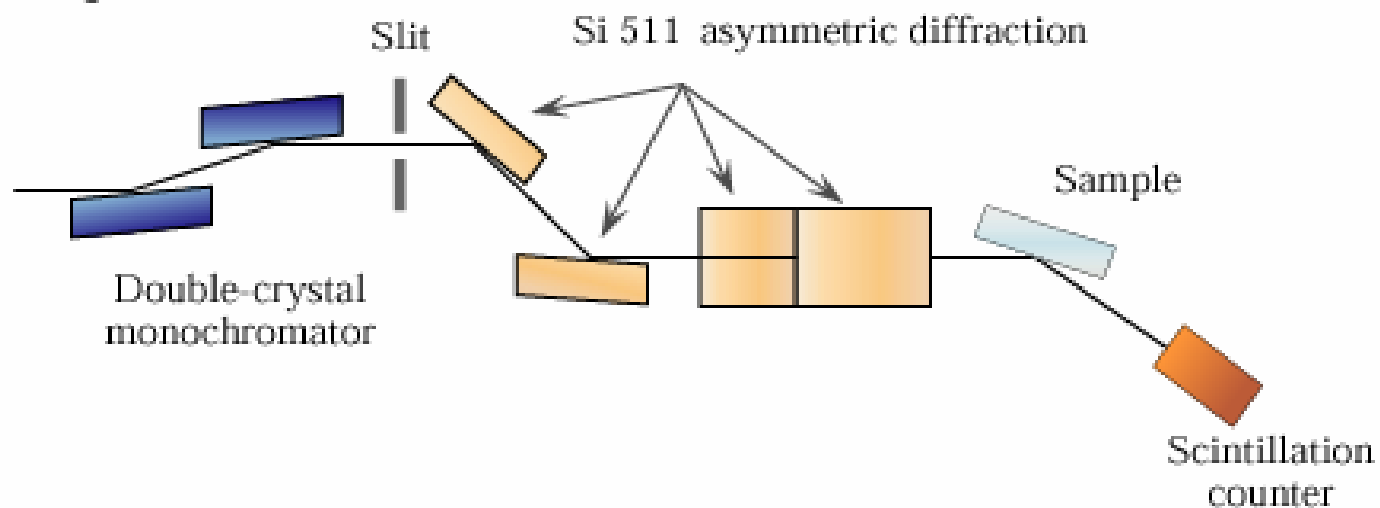
A package process for fabrication of lasers with various wavelength



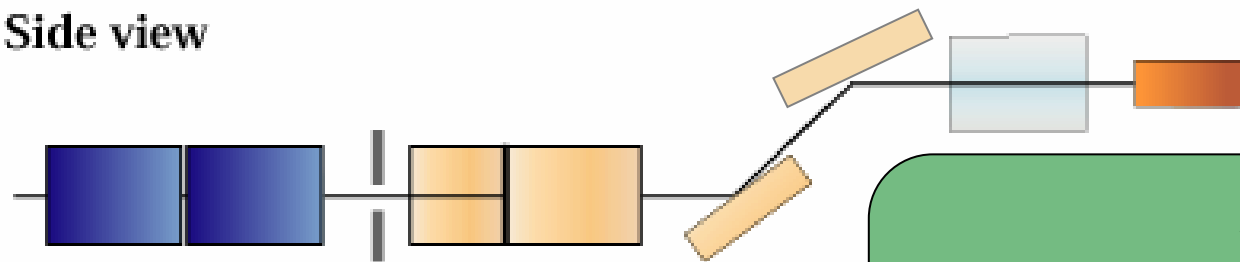
Narrow-strip selective metal-organic vapor phase epitaxy (MOVPE)

X-ray micro-beam

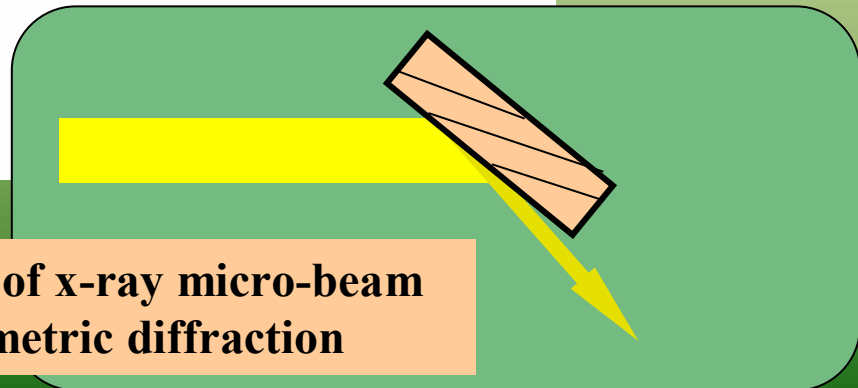
Top view



Side view

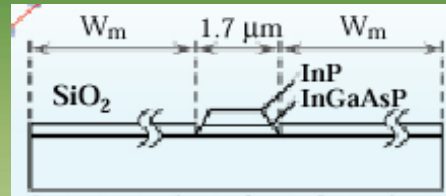
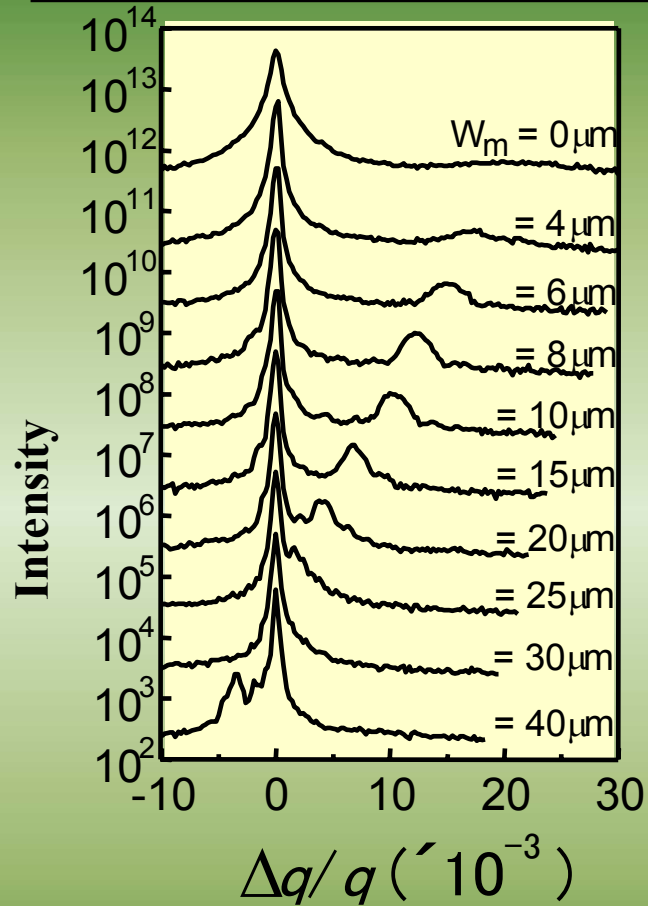


Formation of x-ray micro-beam with asymmetric diffraction

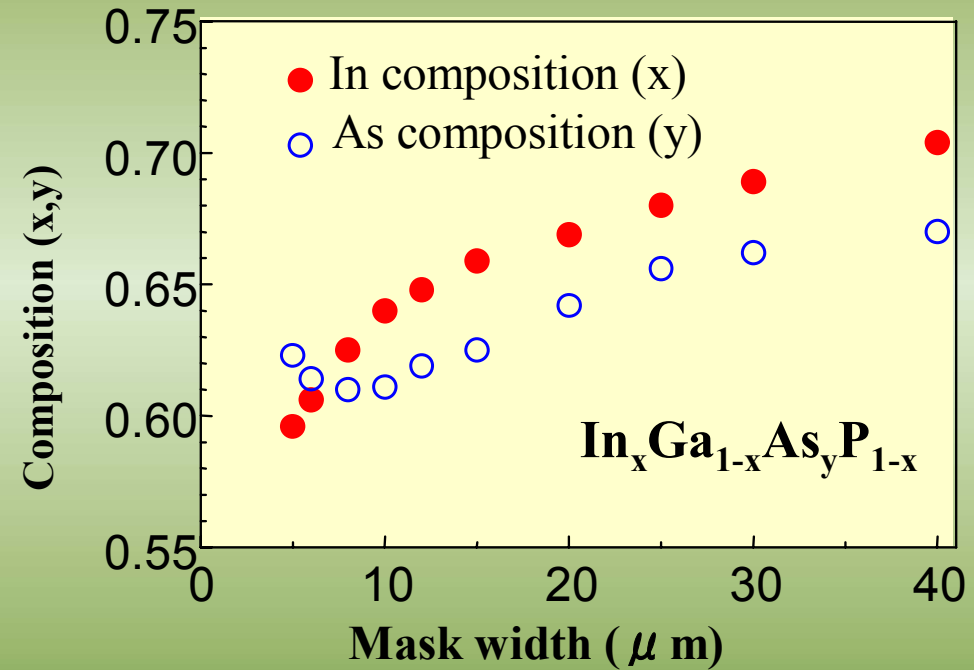




Determination of process condition



S.Kimura et al., APL 77(2000) 1286.

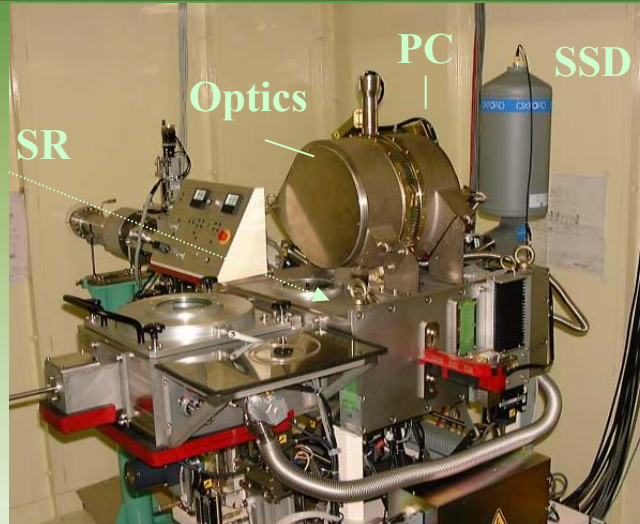


Mask width dependence of composition (x,y)

40% up on emission efficiency of semiconductor laser

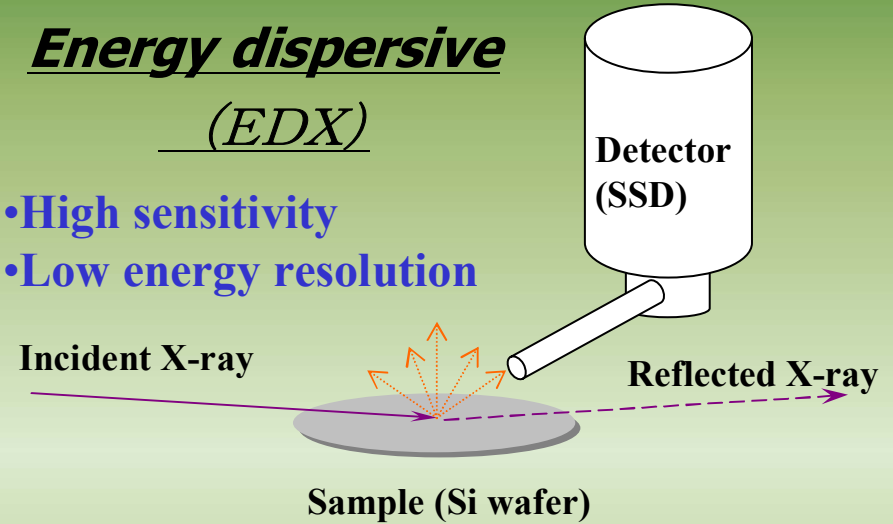


X-ray fluorescence analysis



Energy dispersive (EDX)

- High sensitivity
- Low energy resolution

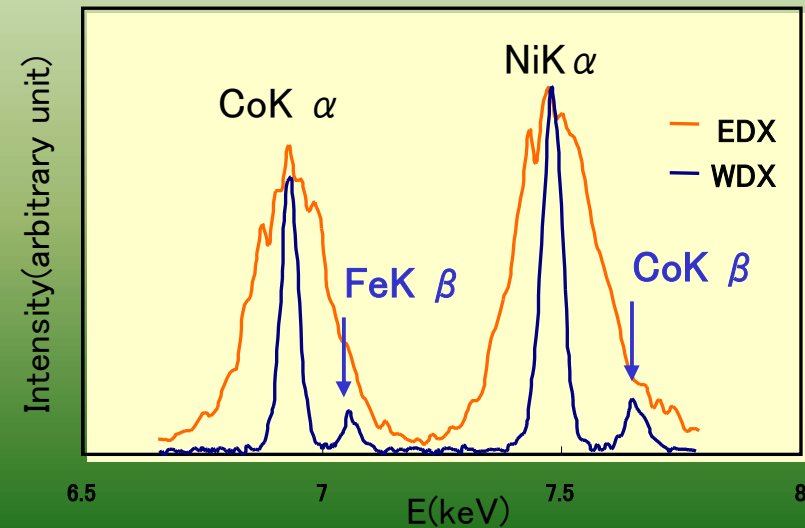
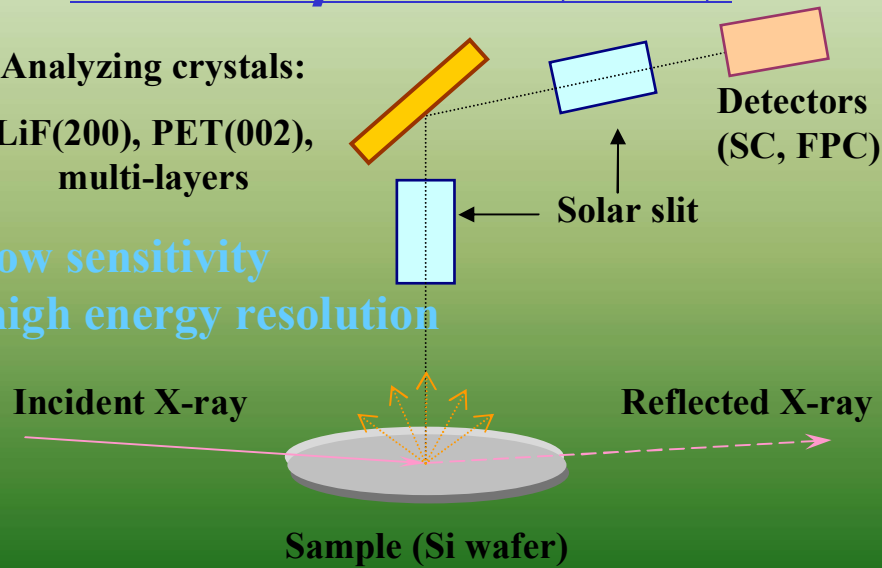


Wave dispersive (WDX)

Analyzing crystals:

LiF(200), PET(002), multi-layers

- low sensitivity
- high energy resolution





Ultra-low detection limit

M. Takemura in TOSHIBA

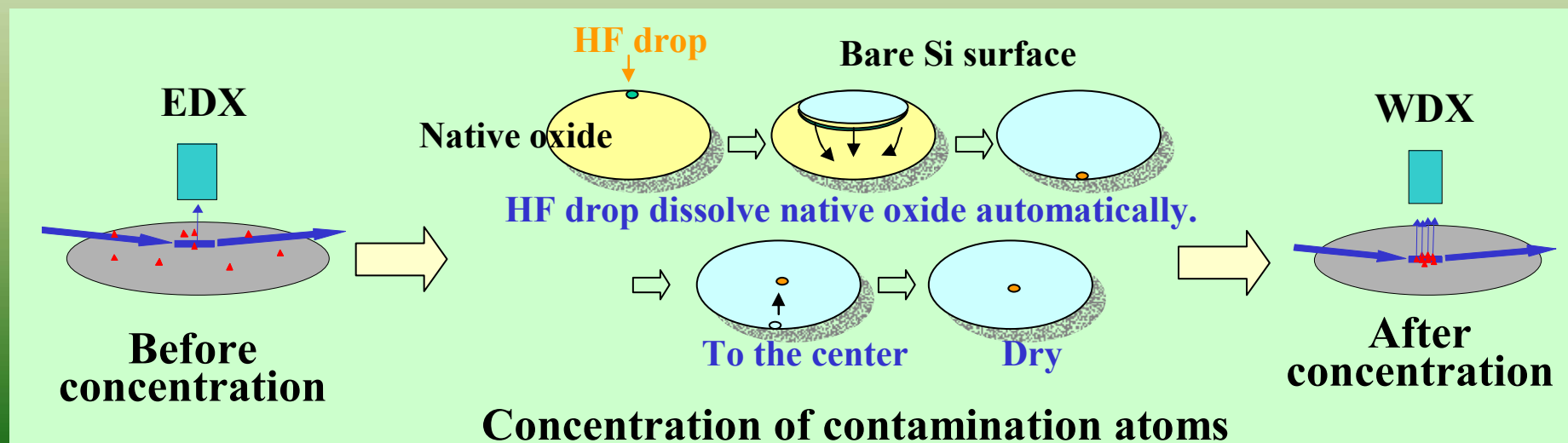
	2002	2005	2008	2011
size(nm)	130	100	70	50
production(bit)	1G	2G	-	16G
allowance ($\times 10^8$ atoms/cm ²)	≤ 4.4	≤ 2.5	≤ 2.1	≤ 1.8

ITRS road map

	Before concentration	After concentration
Ni	5×10^8	4×10^6
Cu	5×10^8	4×10^6
Al	2×10^{11}	8×10^8

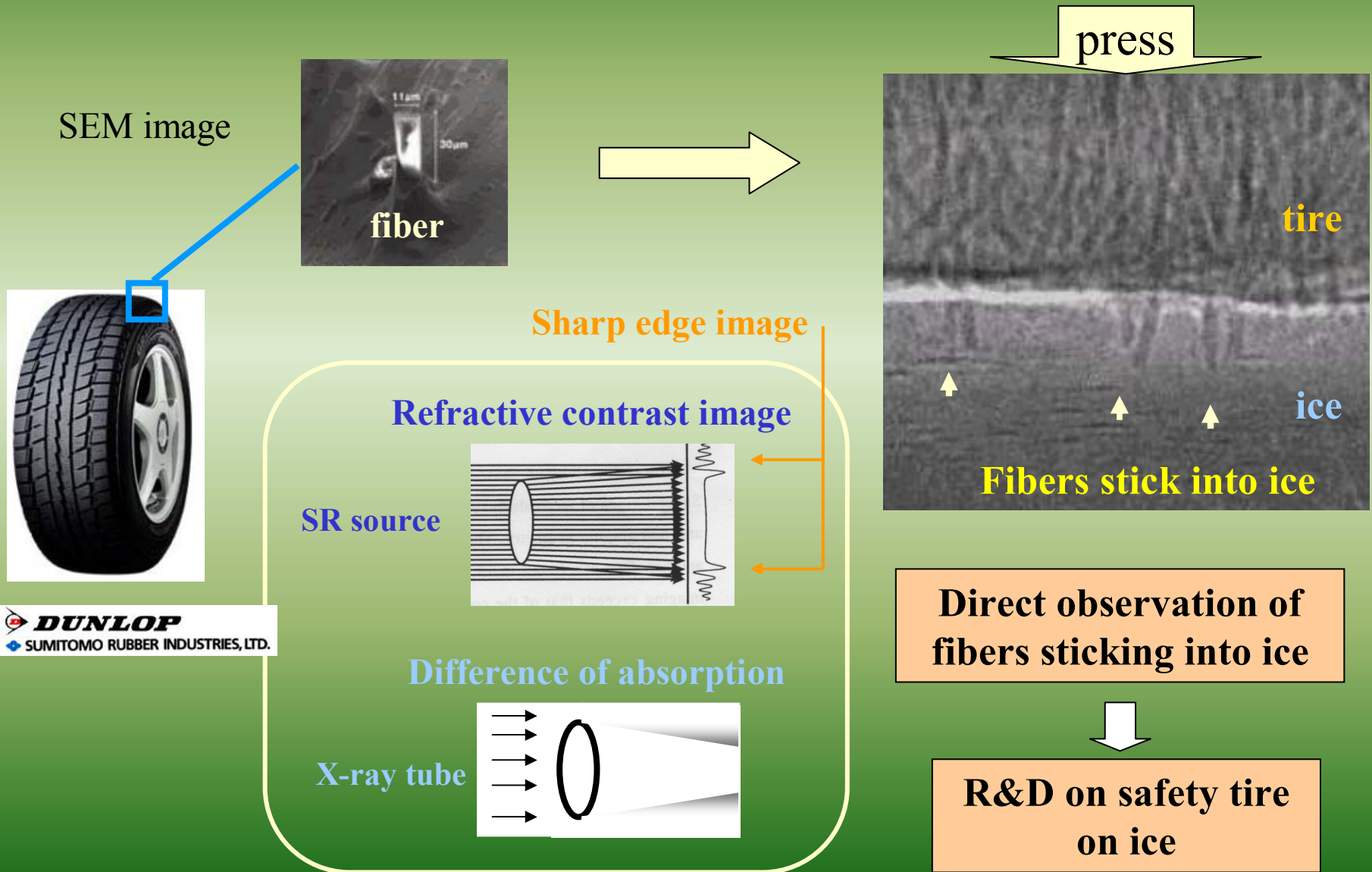
atoms/cm²

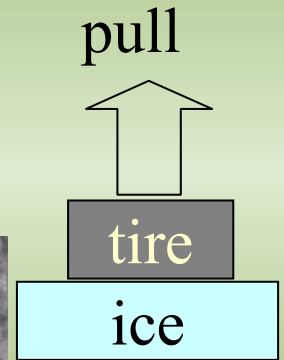
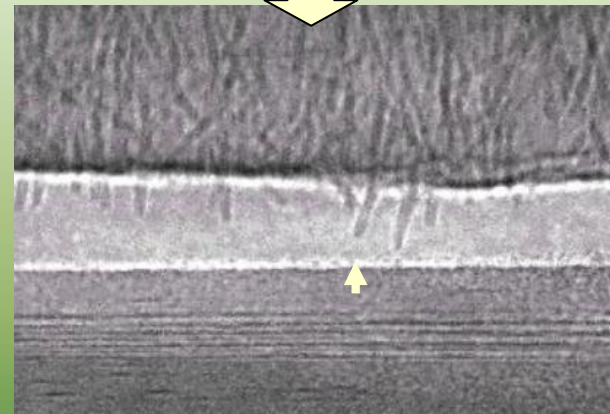
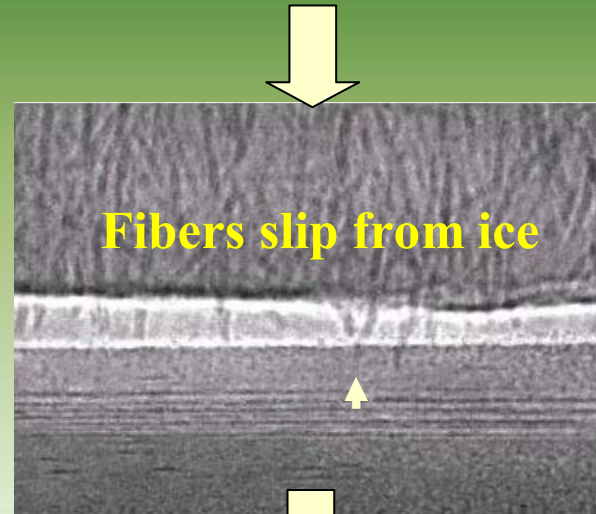
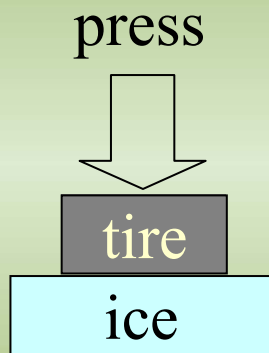
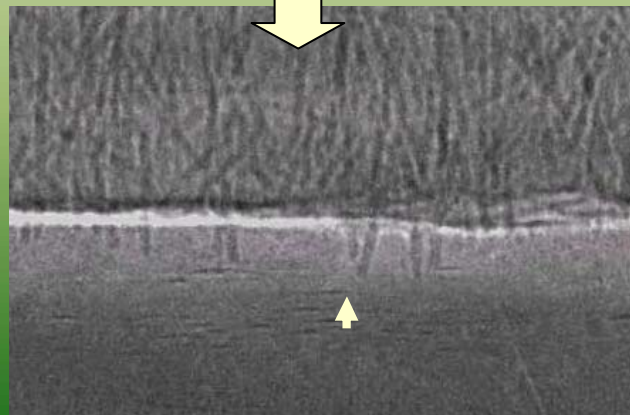
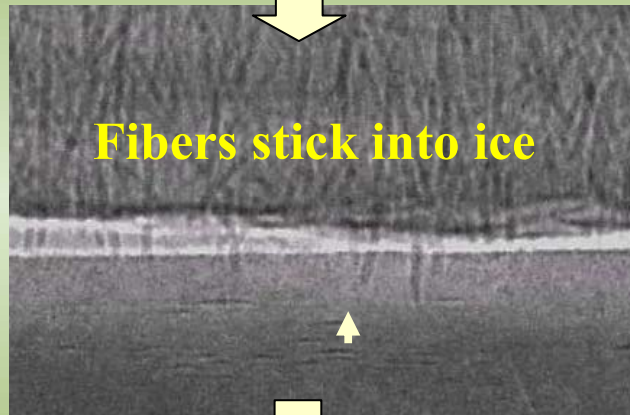
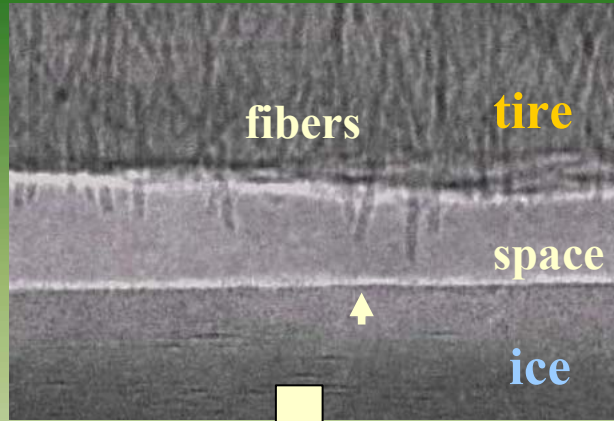
$$4 \times 10^6 \text{ atoms/cm}^2 = 4 \text{ atoms/100 } \mu\text{m}^2$$





Direct observation of fibers in safety tire







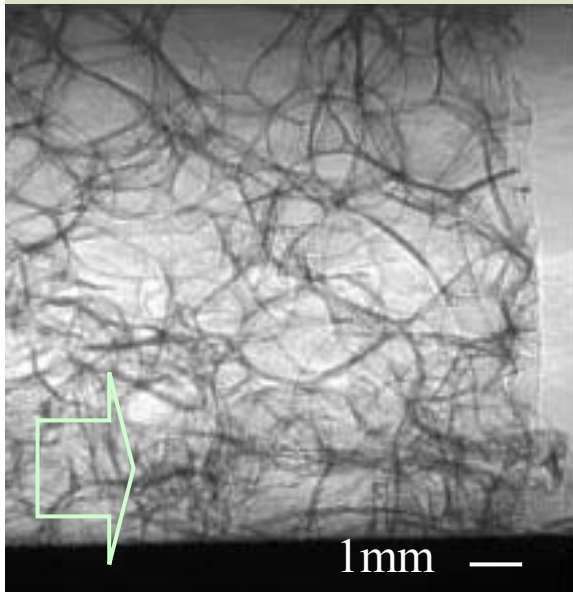
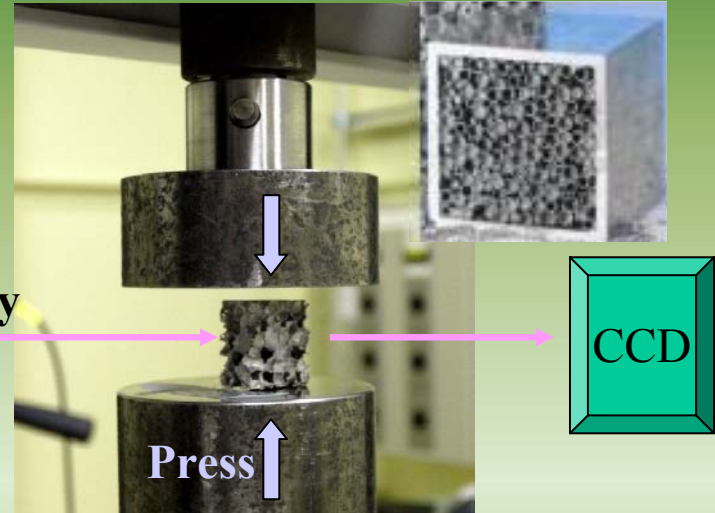
Observation of crush of babbles in Al

T. Watanabe in Kobelco Research Institute

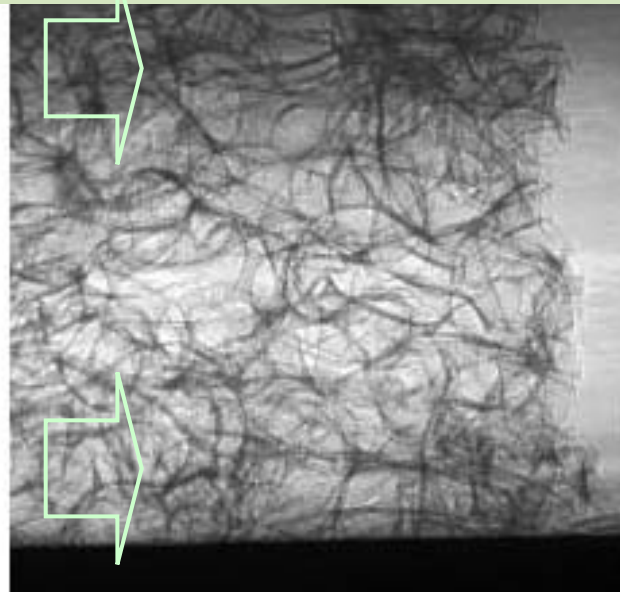


Shock absorber for crush

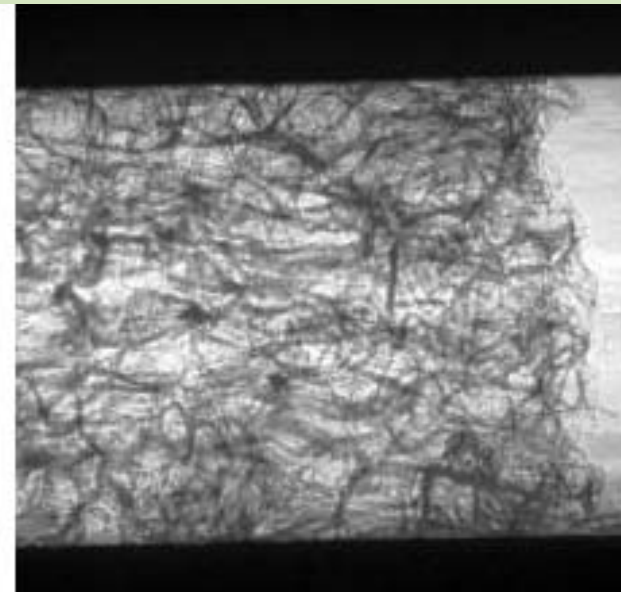
Images stored during 2 sec



Crush from the bottom side

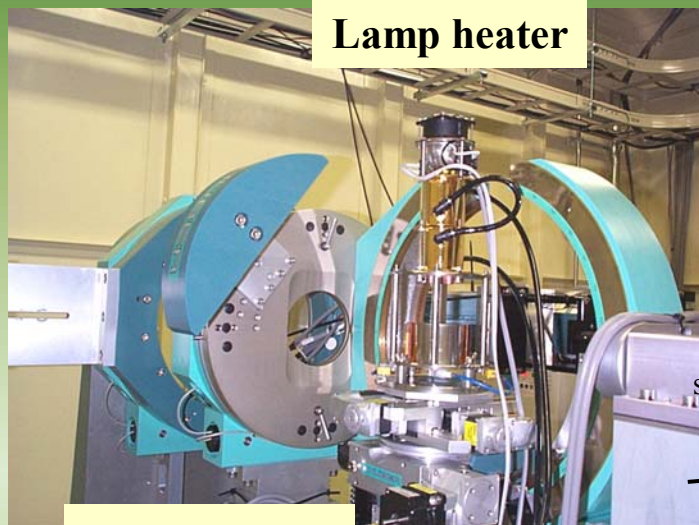


Crush from the both sides



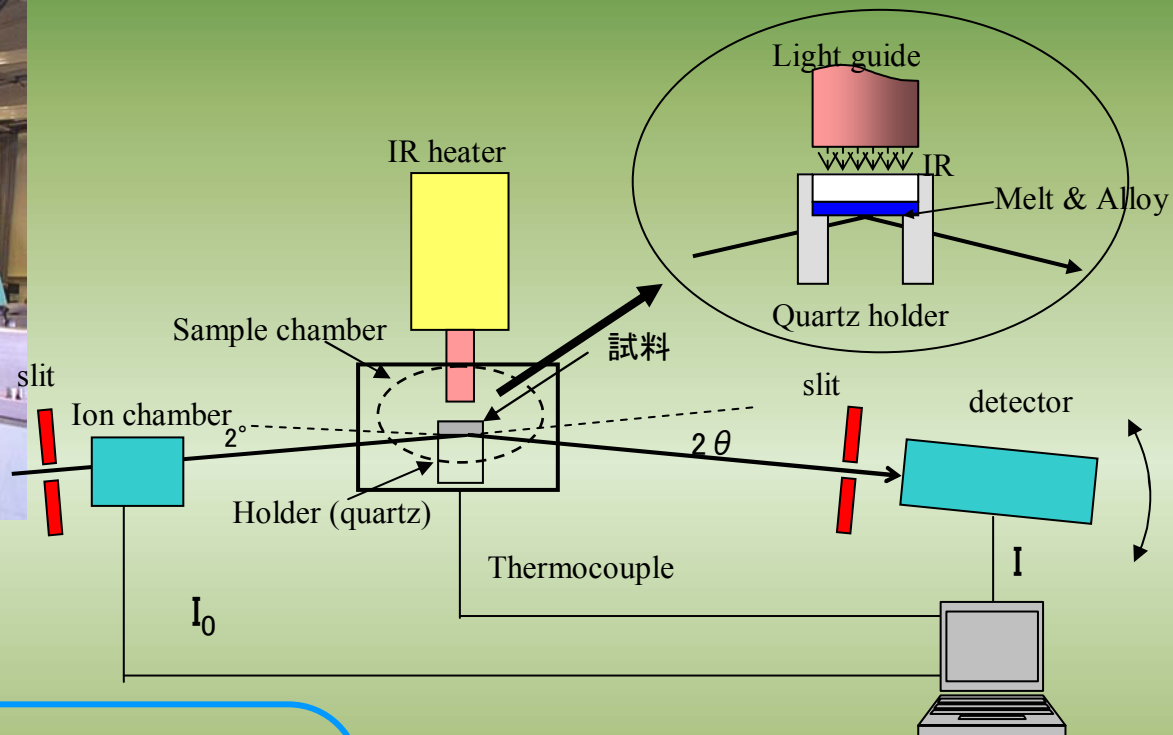
Crush all

In-situ observation of alloying of galvanized steel by Zn



Lamp heater

Diffractometer



Rust preventive coat

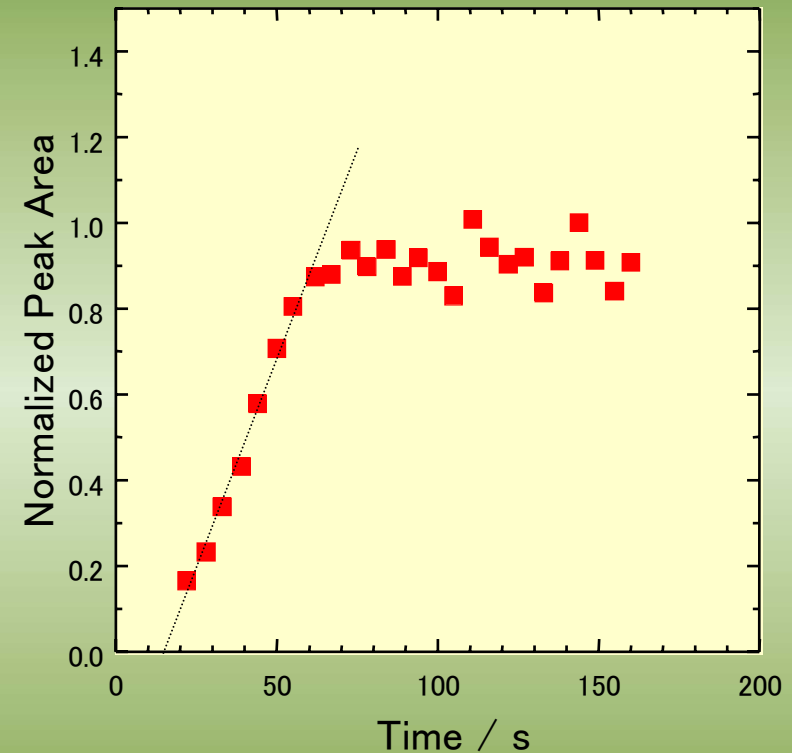
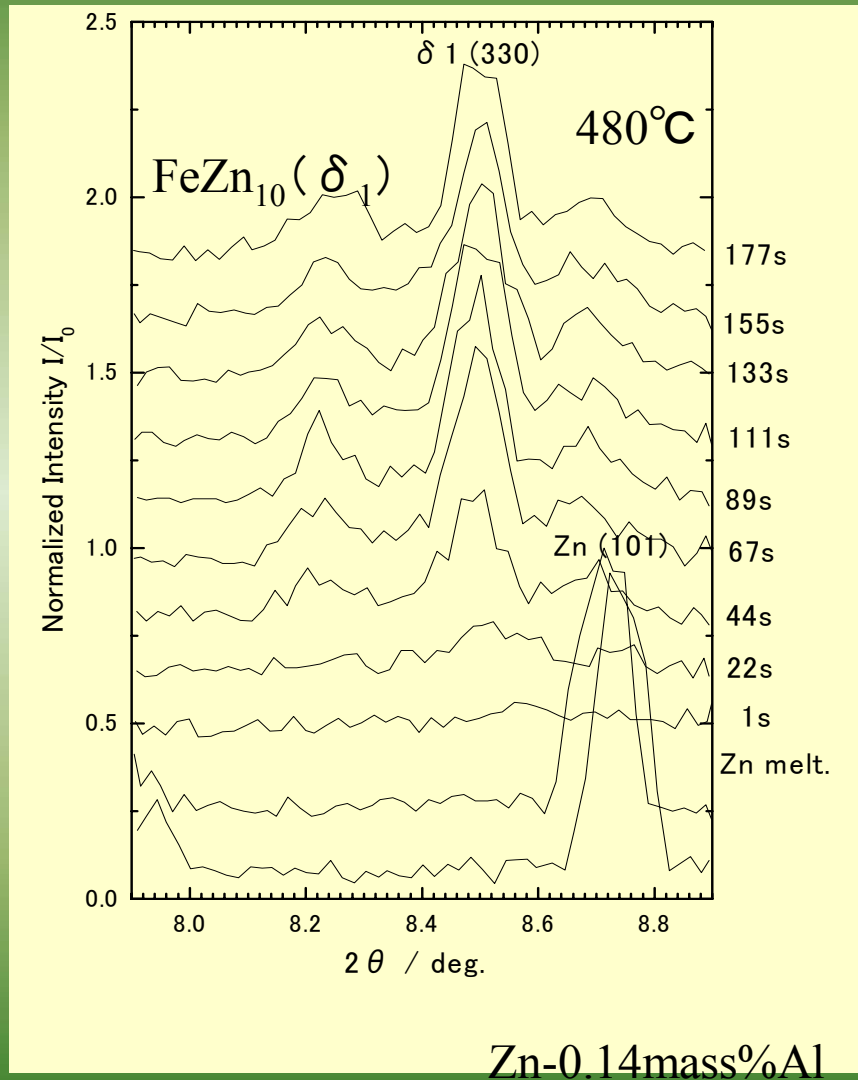
めっき(Zn)層
Fe-Zn
アウトバースト組織
Fe-Zn 母材

Zn
Fe-Zn alloy
Fe (base)





Alloying process of Zn on steel



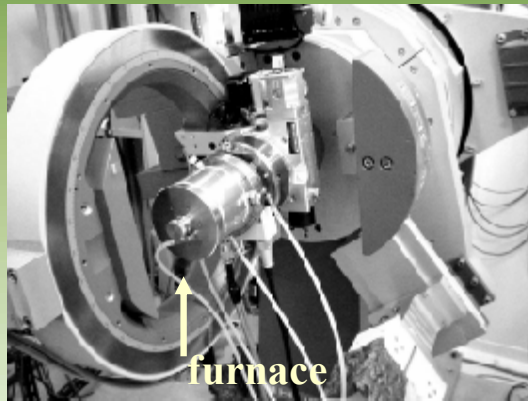
Amount of δ_1 crystals $\propto \sqrt{t}$
(integrated intensities)

⇒ Controlled by diffusion process

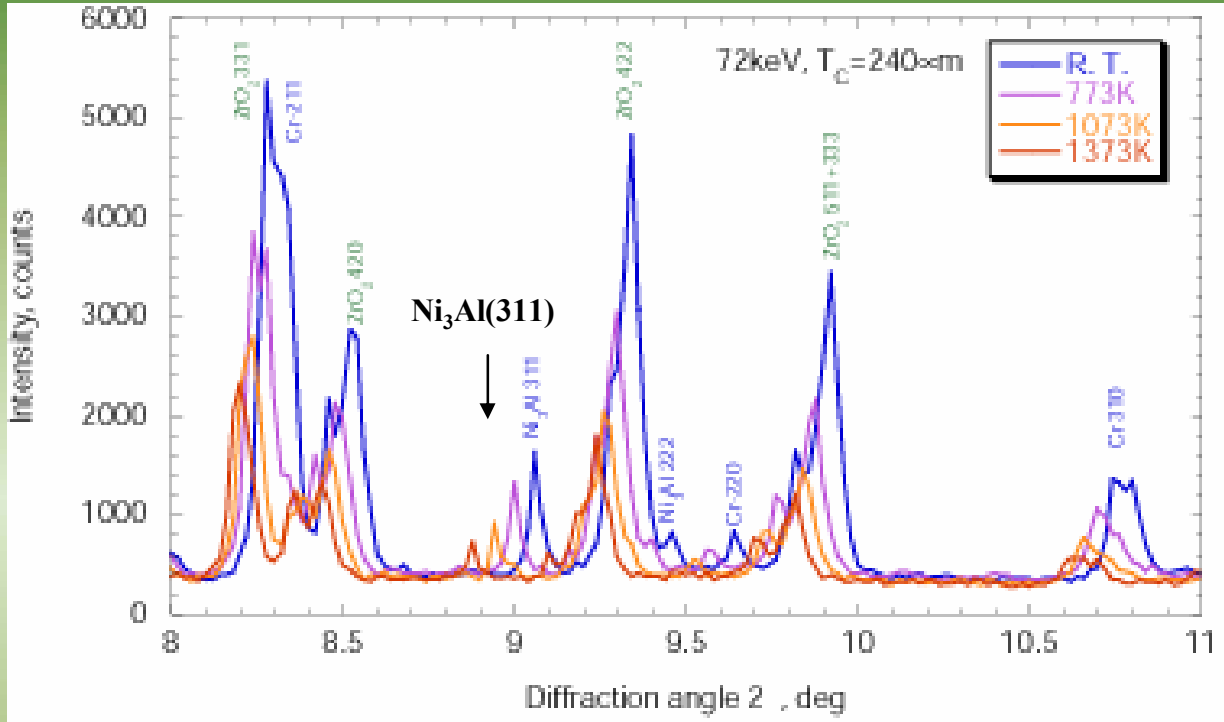
Variation of diffraction profiles on alloying



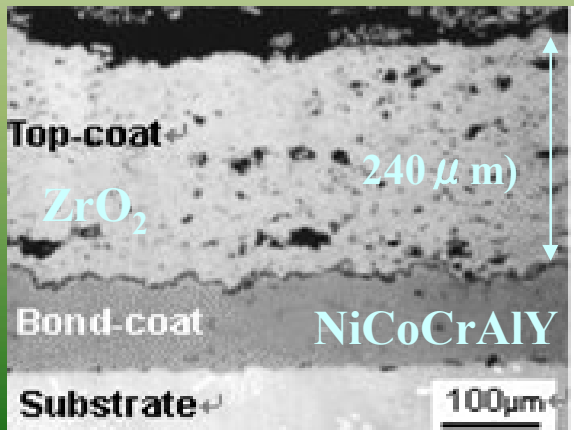
Characterization of inner stress in coats on turbine blades



Diffractometer



Coat to protect blades from high temperature gas

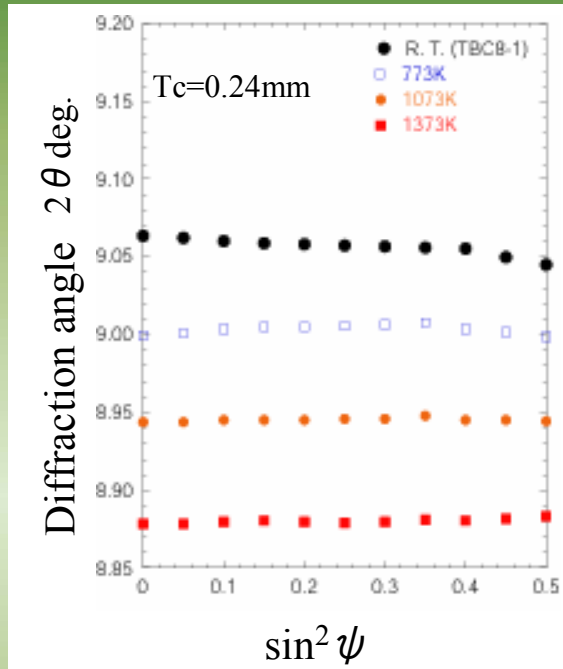


Variation of diffraction profiles on heating



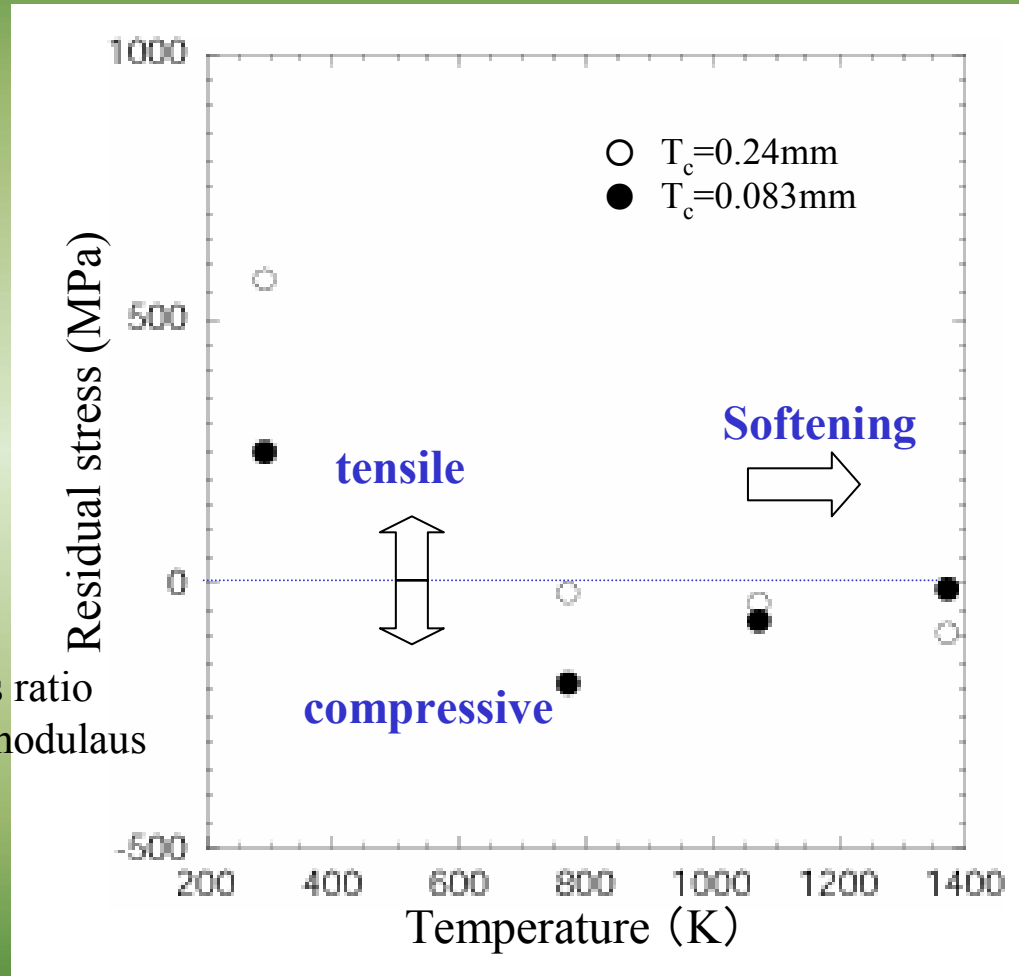
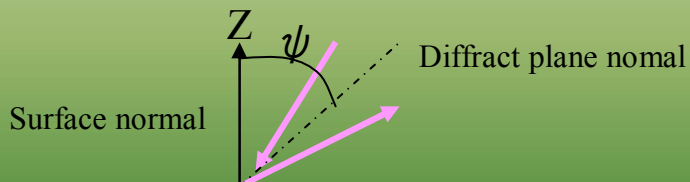


Temperature dependence of residual stress in bond-coat



$2\theta_\psi \propto \text{constant} - K\sigma \sin^2\psi$
 $K = (\tan \theta_0) 2(1 + \nu)/E$

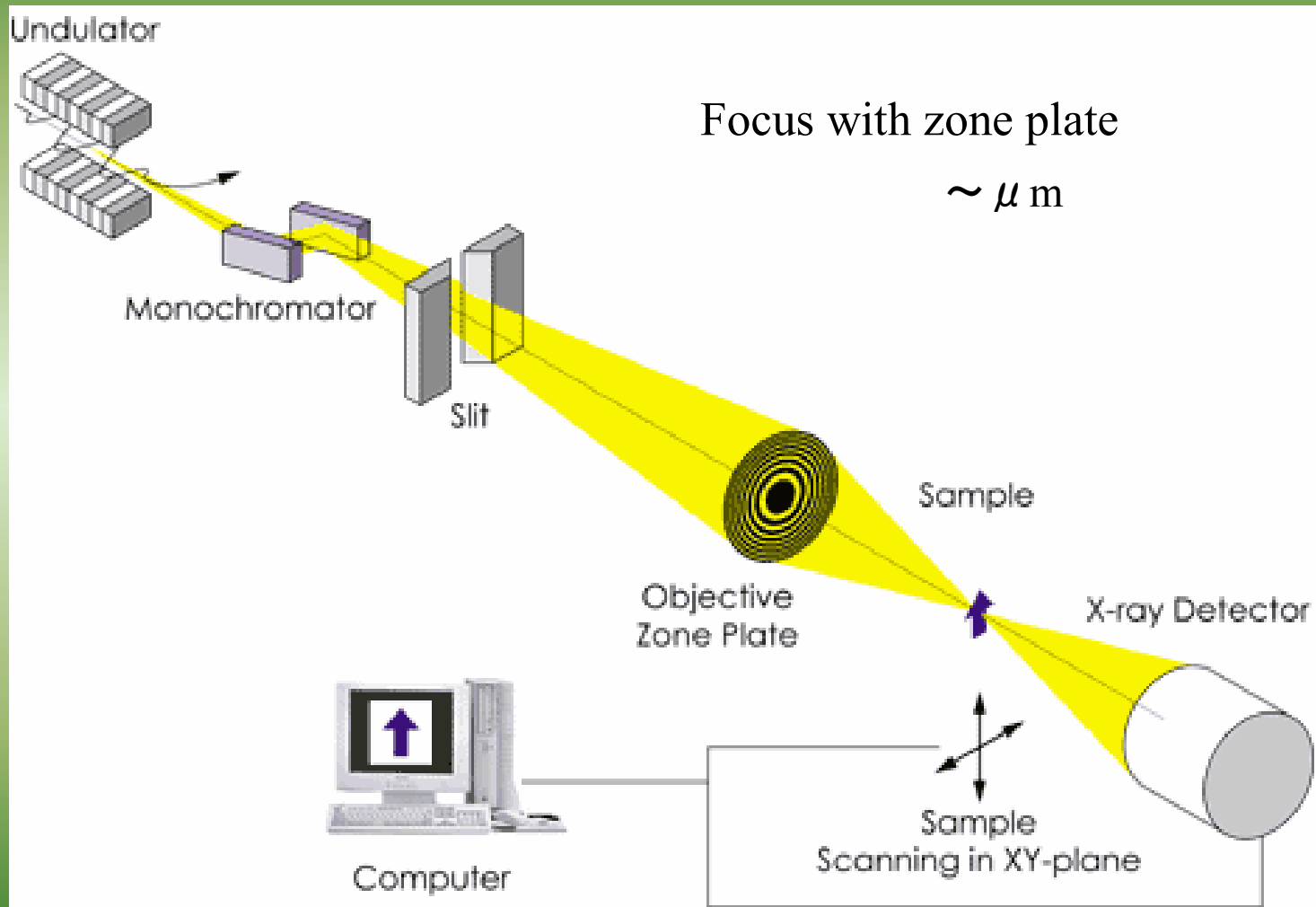
ν : Poisson's ratio
 E : Young's modulus



Temperature dependence of residual stress in bond-coat



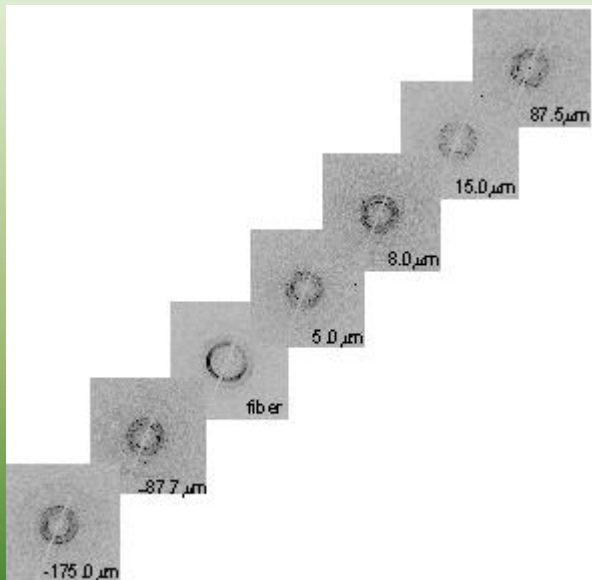
X-ray micro-beam with zone plate



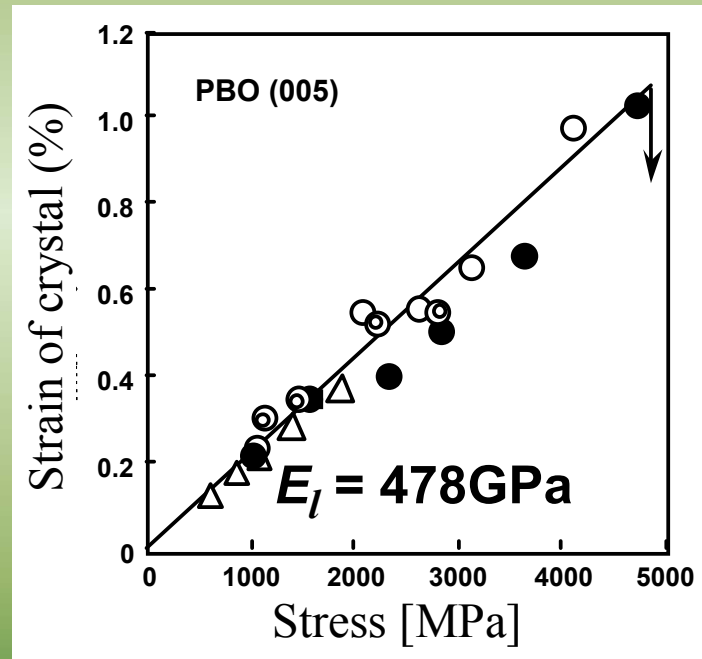


Structural analysis of a single fiber

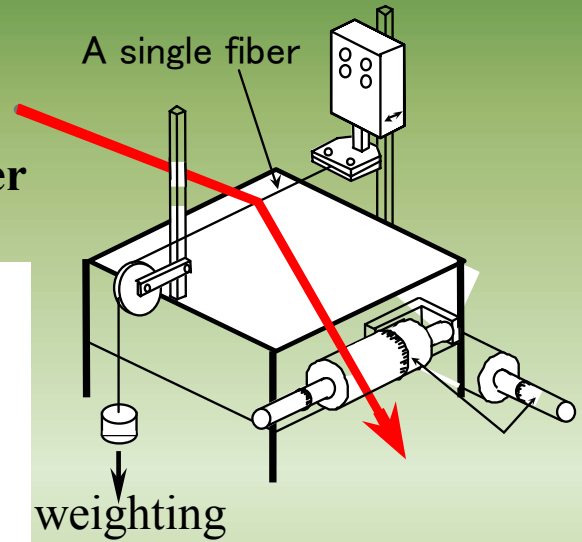
Structural change at local parts in complex fibers



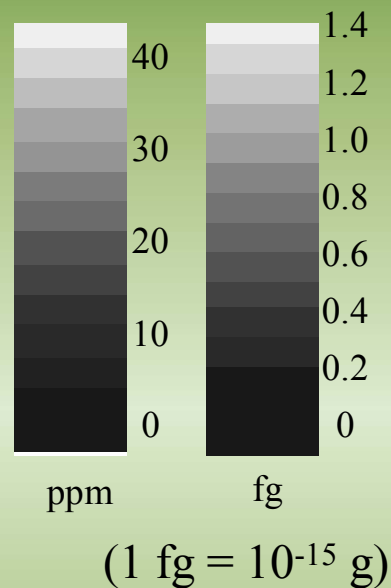
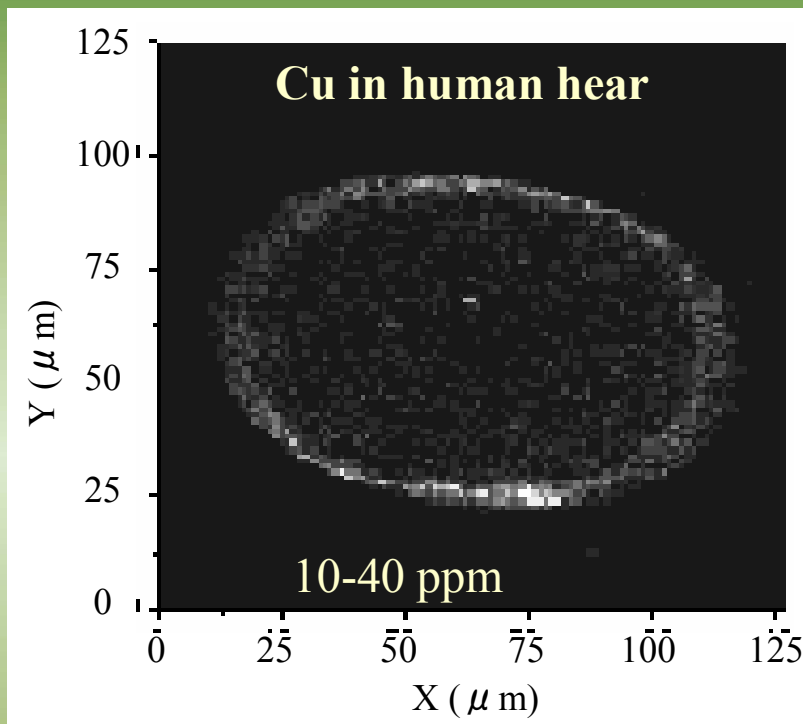
Stress-strain of a PBO single fiber
0.01 mm in diameter



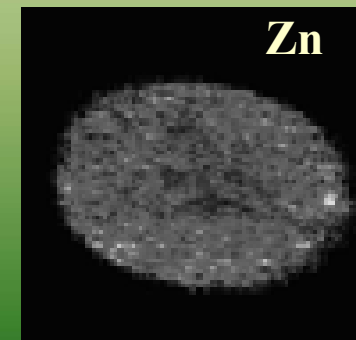
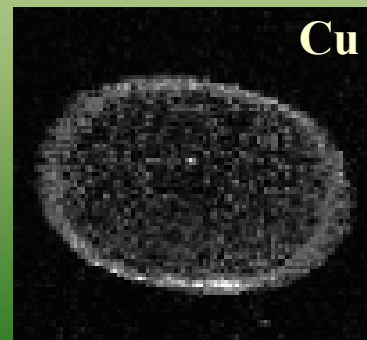
X-ray



2-D mapping of a very small amount of metals with x-ray fluorescence analysis



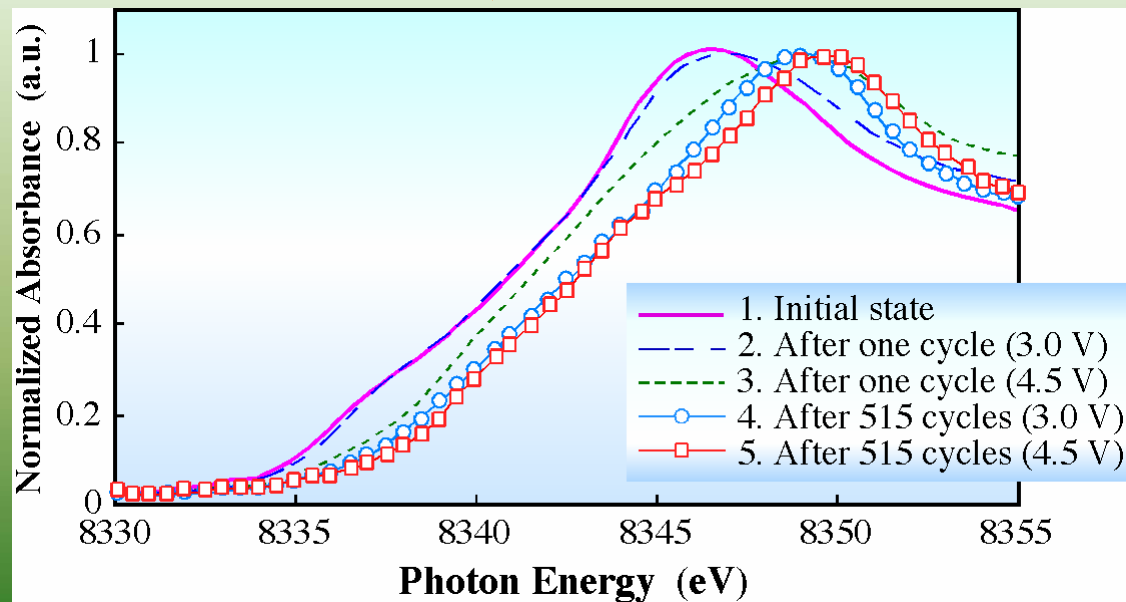
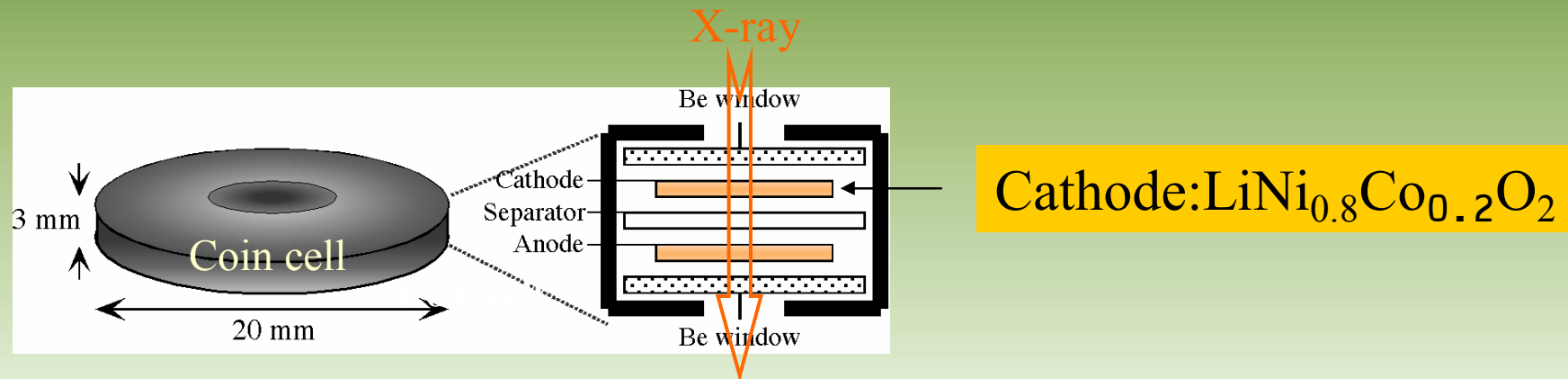
Influence of special water from deep sea on the body





Capacity fading on Li ion battery during charge/discharge cycles

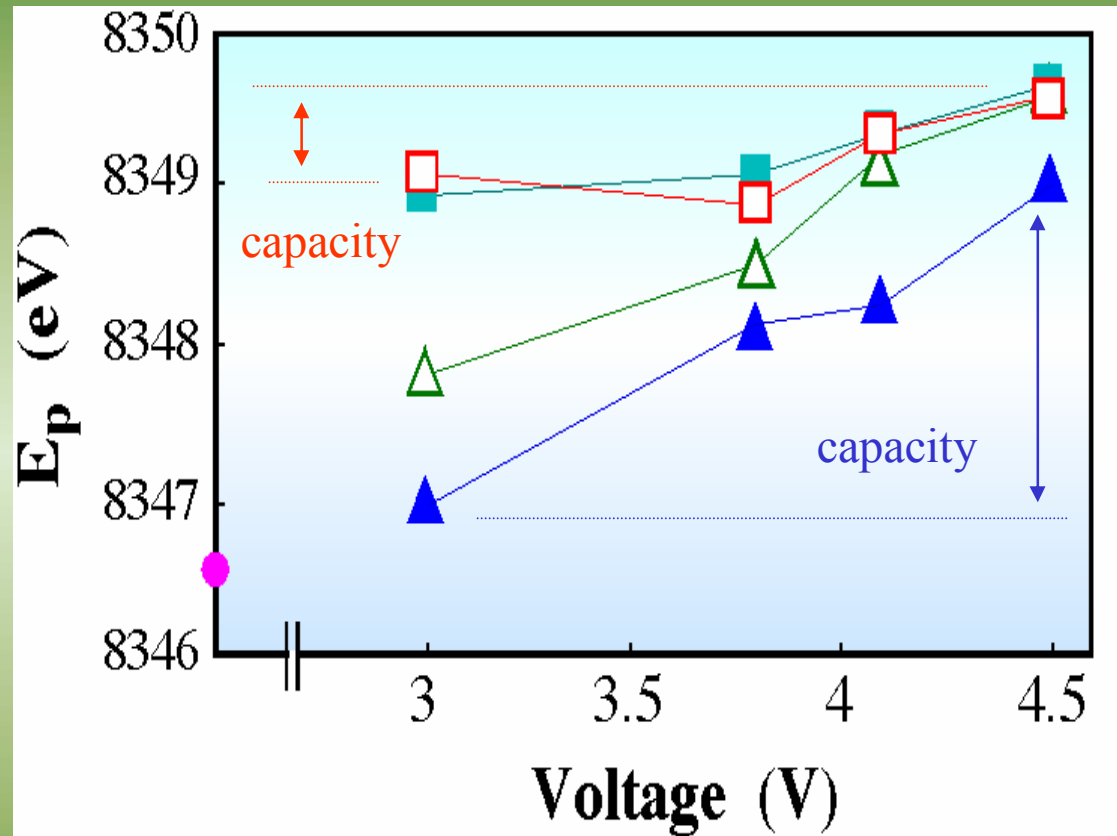
—In-situ XAFS study on cathode during cycling of battery—



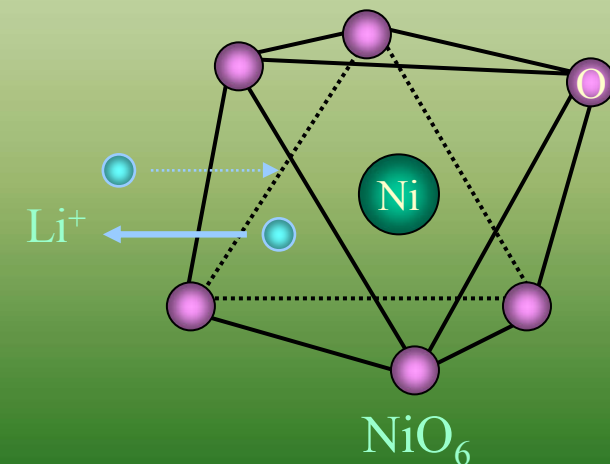
Ni K-edge XANES spectra of $\text{LiNi}_{0.8}\text{Co}_{0.2}\text{O}_2$



Decrease in capacity due to no return of Li into cathode

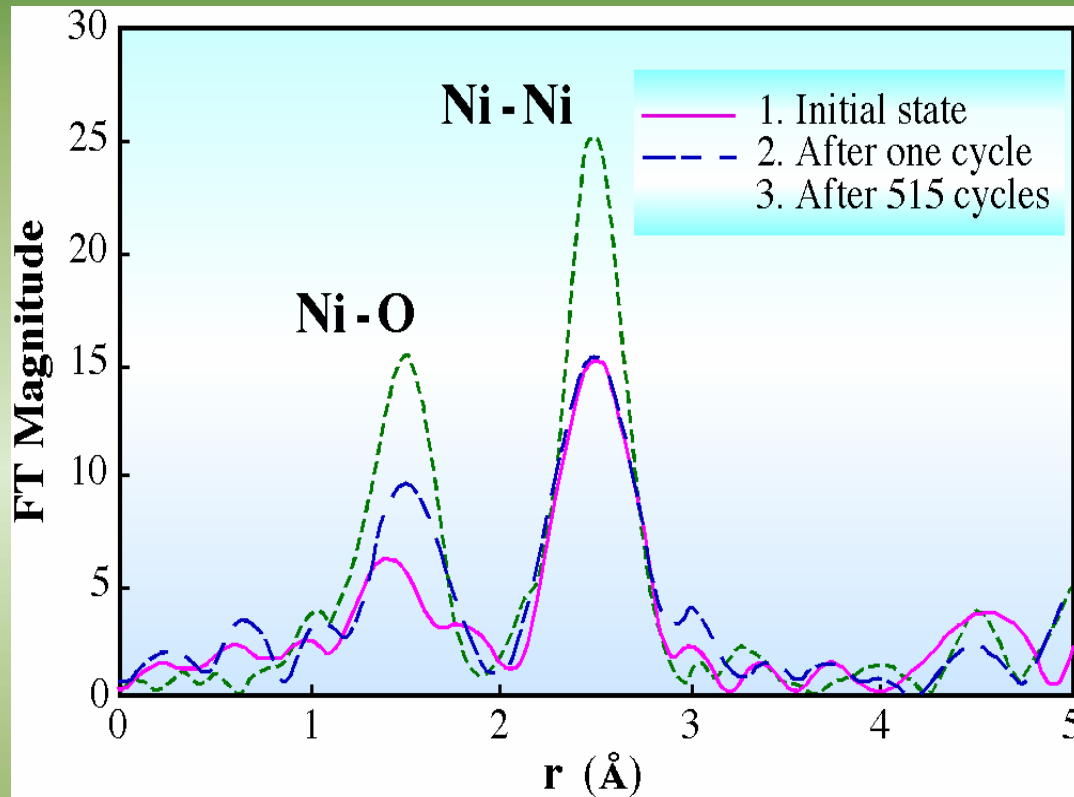


- 1. Initial state
- ▲ 2. After one cycle
- 3. After 515 cycles
- △ 4. 80 °C × 3 days
- 5. 60 °C × 25 days



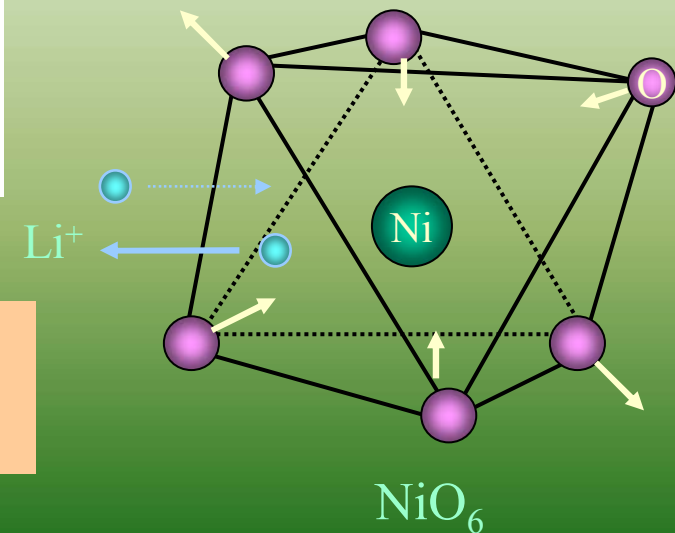


Mechanism of the capacity fading



Initial: distorted NiO_6 octahedron
After fading: regular NiO_6 octahedron

Jahn-Teller distortion

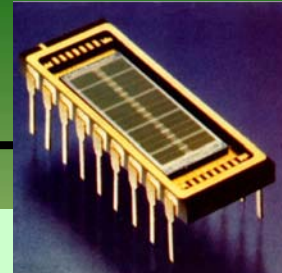


- No detectable with other techniques
- How situation : Research, Development,
Production
 - R&D : Excellent characterization
 - Development of process :
regular measurement according to plan
 - Test : Quality & Quantity & Time
 - Response to trouble : Speed

How can we (SR) reply on request?

Situation in Japan

- No detectable with other techniques
- How situation : Research, Development, Production
 - R&D: Excellent characterization



Structural analysis of thin films of electronic devices

- Development of process :

Determination of process conditions for laser

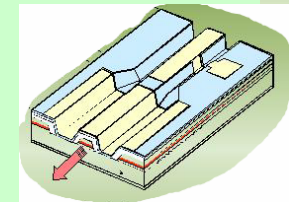
Imaging of tire and bobbed Al

- Test: Quality & Quantity & Time

Not actualized in Japanese facilities

- Response to trouble : Speed

No answer





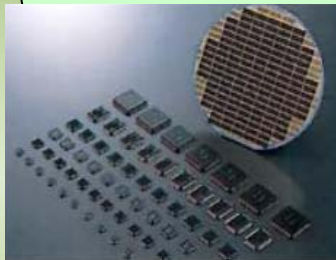
Industrial Applications in Japan

- Films for ULSI, semiconductors
- HDD, DVD
- Semiconductor laser

- Steel & rust preventive coat
- Various coats to prevent heat, stress, etc.
- Al including bubbles

Synchrotron radiation

electronics



Metals



XAFS, XPS
Diffraction; GIXD, Powder
Reflectivity, Grazing incidence x-ray
fluorescence technique
Fluorescence analysis
Imaging, Micro-beam

Soft Materials



- Tires
- Fibers



Others

- Building materials
- Catalysis
- Insects

Energy & Environment



- Batteries: fuel cell & Li-ion
- Analysis of contamination elements
- Catalysts for environment